Overview

HP Z4 G5 Workstation



Front

- 1. Integrated Front Handle
- 2. Power Button
- 3. HDD Activity LED
- 4. Headphone/microphone combo

- 5. Front I/O Premium²:
 - 2 SuperSpeed USB Type-C $^{\rm TM}$ 20 Gbps signaling rate (USB Power Delivery 3.0),
 - 2 SuperSpeed USB Type-A 5 Gbps signaling rate [left-most Type-A port supports BC1.2 (Battery Charging)]

Front I/O Entry:

- 4 SuperSpeed USB Type-A 5 Gbps signaling rate [left-most Type-A ports supports BC1.2 (Battery Charging)]
- 6. SD Card Reader
- 7. 2x External 5.25" bay¹

¹Only 1 external 5.25" drive configurable from factory ²Premium Front IO is shown on photography

Overview

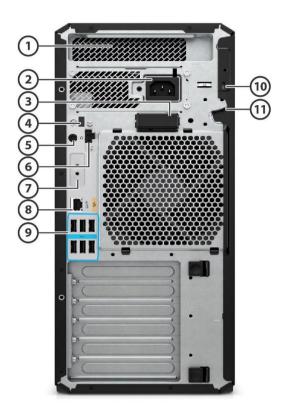


- 1. 1 Intel® Xeon® Processor (Sapphire Rapids)
- 2. 8 DIMM slots for DDR5 ECC Memory
- 3. •Slot 1: PCIe x16 Gen5
 - •Slot 2: PCIe x4 Gen4
 - •Slot 3: PCIe x4 Gen4
 - •Slot 4: PCIe x16 Gen4
 - •Slot 5: PCIe x16 Gen4
- 4. 2 PCIe x4 Gen4 configurable with M.2 SSDs

Internal View

- 5. 5 SATA ports
- 6. 3 Internal USB Ports. 1 single USB2.0 port, 1 dual USB2.0 port, 1 USB3.0 port (for the SD card reader)
- 7. 2 Internal 3.5" bays
- 8. 2 External 5.25" bays
- 9. Choice of 525W, 775W, or 1125W 90% Efficient Power Supplies
- 10. 1 Internal NVMe connector to front removable M.2 carrier

Overview



Rear View

- 1. Integrated Rear Handle
- 2. Power Connector (Choice of 525W, 775W, or 1125W 90% Efficient Power Supplies)
- 3. External Antenna
- 4. Rear Power Button
- 5. Audio In/Out

Form Factor Tower

Operating Systems

Preinstalled:

- Windows 11 Pro for Workstations²
- Windows 11 Pro for Workstations (preinstalled with Windows 10 Pro for Workstations Downgrade),2,3
- Ubuntu Linux 22.04⁴
- HP Linux®-ready (minimal OS ready for customer OS installation)⁵

License Only:

 Red Hat® Enterprise Linux® Desktop Workstation (includes paper license with 1 year support; no preinstalled OS)⁶

6. Manageability Port (optional)

8. 1 RJ-45 Integrated LAN Port (1GbE AMT)

9. 6 SuperSpeed USB Type-A 5Gbps Signaling Rate

7. Flex I/O Module (optional)

10. Kensington Lock Slot

11. Padlock loop

Supported:

- Windows 11, version 22H2, 21H2²
- Windows 10, version 22H2, 21H2²
- Red Hat® Enterprise Linux® Workstation 8 & 9⁶
- SUSE Linux® Enterprise Desktop 156



Overview

Ubuntu 20.04 & 22.04 LTS⁵

Web-supported only:

- Windows 11 Enterprise^{2,1}
- Windows 10 Enterprise^{2,1}
- ¹ Windows Enterprise sold separately and requires that customer have an enterprise license from Microsoft.
- ² Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.
- ³This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.
- ⁴ Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply and additional requirements may apply over time for updates.
- ⁵A certified preloaded version of Ubuntu® 20.04 LTS is available from HP for this platform. Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply, and additional requirements may apply over time for upgrades.

⁶For detailed Linux[®] OS/hardware support information, see:

http://www.hp.com/support/linux hardware matrix

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282



Overview

Processors

				Frequenc (GHz)	У		Max Memory Speed (MT/s)		
Name ¹	Cores	Threads	Base Clock Speed	Intel® Turbo Boost Max All-Core Frequency ²	Intel® Turbo Boost Max Single-Core Frequency ²	Cache (MB)	1 DIMM per Channel	2 DIMM per Channel	TDP (W)
Intel® Xeon® W7-2495X	24	48	2.5	3.3	4.6	45	4800	4400	225
Intel® Xeon® W7-2475X	20	40	2.6	3.4	4.6	37.5	4800	4400	225
Intel® Xeon® W5-2465X	16	32	3.1	3.7	4.5	33.75	4800	4400	200
Intel® Xeon® W5-2455X	12	24	3.2	3.9	4.4	30	4800	4400	200
Intel® Xeon® W5-2445	10	20	3.1	4.0	4.4	26.25	4800	4400	175
Intel® Xeon® W3-2435	8	16	3.1	4.0	4.3	22.5	4400	4400	165
Intel® Xeon® W3-2425	6	12	3.0	3.7	4.2	15	4400	4400	130
Intel® Xeon® W3-2423	6	12	2.0	3.1	4.0	15	4400	4400	110

Notes:

- Xeon W-2400 processors all feature Intel® vPro® Technology³
- Xeon W-2400 processors all support Hyper-Threading
- Xeon W-2400 processors do not offer integrated graphics

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

² Intel Turbo Boost Max (ITBM) performance varies depending on hardware, software, and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

Intel vPro® requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro® Essentials and Enterprise vary. See http://intel.com/vpro

Overview

Color Black Convertibility Nο

Expansion Slots (see system board section for •Slot 2: PCIe x4 Gen4 more details)

•Slot 1: PCIe x16 Gen5 •Slot 3: PCIe x4 Gen4 Slot 4: PCIe x16 Gen4 Slot 5: PCIe x16 Gen4

1 internal 3.5" bays

Expansion Bays (see storage section for more 2 external 5.25" bays

details)

Front I/O Front I/O Premium: 2 SuperSpeed USB Type-C™ 20 Gbps signaling rate (USB Power Delivery 3.0), 2

SuperSpeed USB Type-A 5 Gbps signaling rate, 1 headphone/microphone combo, SD card reader

(optional). [left-most Type-A ports supports BC1.2 (Battery Charging)]

Front I/O Entry: 4 SuperSpeed USB Type-A 5 Gbps signaling rate, 1 headphone/microphone combo, SD

card reader (optional). [left-most Type-A ports supports BC1.2 (Battery Charging)]

Internal I/O [5] 3 Internal USB ports and 5 SATA ports.

Rear I/O Audio In/Out, 6x SuperSpeed USB Type-A 5Gbps signaling rate, 1 RJ-45 Integrated LAN port (1GbE AMT)

Optional: Flex I/O Module

Optional I/O Flex I/O Module (Serial Port v3, Dual USB-A 3.2 Gen1, USB-C 3.2 Gen2, 10GbE single port, 2.5GbE LAN

single port, 1 GbE single port, 1 GbE Fiber single port LC, WiFi6 + BT5.2 WLAN w/ INTAnt)

External Antenna

On-board RAID Support SATA RAID 0 Striped Array

SATA RAID 1 Mirrored Array SATA RAID 10 Striped/Mirrored SATA RAID 5 Parity Array

Chassis Dimensions (H x Footprint:

WxD)

H: 15.2" (386 mm) W: 6.65" (169 mm) D: 17.5" (445 mm) Maximum:

H: 15.2" (386 mm) W: 6.65" (169 mm) D: 18" (458.6 mm) H: 22.5" (572 mm)

Packaged Dimensions

W: 12.4" (314 mm) D: 22.2" (563 mm)

Palletization Profile 6 units x 3 layers = 18 units per pallet

1200x1000x1836mm (pallet included)

Rack Dimensions 4U

Weight Exact weights depend upon configuration (System weight only).

Minimum: 10.5 kg (23.2 lbs.) Typical: 12.6 kg (27.8 lbs.) Maximum:19.5 kg (42.9 lbs.)

Temperature Operating: 5° to 40°C (40° to 104°F)1

Non-operating: -40° to 60°C (-40° to 140°F)

140°C has been validated for configs up to a 220W CPU, 2x NVIDIA® A4000 graphics cards, 8x64GB of

RAM, 4TB of M.2 storage, 4TB of HDD storage, and a 1125W PSU

Operating: Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb Humidity

Non-operating: 10% to 90%, non-condensing, 35° C maximum wet bulb



Overview

Maximum Altitude (non- Operating: 3.048m (10.000ft) pressurized)6

Non-operating: 9.144m (30.000ft)

NOTE: Above 1524 m (5,000 feet) altitude, maximum operating temperature is reduced by 1°C (1.8°F)

per 305 m (1,000 feet) elevation increase

Power Supply Choice of 80 Plus Gold (90% efficiency at 50% load) Power Supplies:

1125W (Delta Efficiency Report) 775W (Delta Efficiency Report) 525W (Delta Efficiency Report)

NOTE: not all configurations are supported on all power supplies. Configuration support depends on total system power budget and having sufficient number or type of PCIe supplemental power connectors. Confirm power supply and configuration support using configurator on hp.com.

1125W supports up to 600W of auxiliary graphics power (dependent on system configuration)

775W supports up to 400W of auxiliary graphics power (dependent on system configuration)

525W supports up to 100W of auxiliary graphics power (dependent on system configuration)

NOTE: updating graphics after purchase may require additional power distribution cables and/or auxiliary graphics adapters to support the new graphics configuration.

Workstation ISV Certifications

See the latest list of certifications at

http://www.hp.com/united-states/campaigns/workstations/partnerships.html

Chipset

Intel® W790 chipset

Memory

8 DIMM slots, supporting up to 512GB, DDR5 4800 MT/s speed depending on the system configuration

Supported Components

Processors		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	Intel® Xeon® W-2400 Processors				
	Intel® Xeon® W7-2495X	Υ	N		
	Intel® Xeon® W7-2475X	Υ	N		
	Intel® Xeon® W5-2465X	Υ	N		
	Intel® Xeon® W5-2455X	Υ	N		
	Intel® Xeon® W5-2445	Υ	N		
	Intel® Xeon® W3-2435	Υ	N		
	Intel® Xeon® W3-2425	Υ	N		
	Intel® Xeon® W3-2423	Υ	N		

SATA Hard Drives		Factory Configured	Option Kit	Option Kit Part Number
	1TB 7200RPM SATA 3.5in Enterprise HDD ^{1,2}	Υ	Υ	WOR10AA
	2TB 7200RPM SATA 3.5in Enterprise HDD ^{1,2}	Υ	Υ	2Z274AA
	4TB 7200 RPM SATA 3.5in Enterprise HDD ^{1,2}	Υ	Υ	K4T76AA/AT
	8TB 7200RPM SATA 3.5in Enterprise HDD ^{1,2}	Υ	Υ	2Z273AA
	12TB 7200 RPM SATA-6G 3.5in Enterprise HDD ^{1,2}	Υ	Υ	5S461AA

PCIe Solid State Drives

Z Turbo 512GB PCIe-4x4 TLC SSD Module	Υ	Υ	38T80AA
Z Turbo 512GB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Υ	Υ	38T81AA
Z Turbo 1TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Υ	Υ	38T76AA
Z Turbo 1TB PCIe-4x4 TLC SSD Module	Υ	Υ	38T77AA
Z Turbo 2TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Υ	Υ	38T79AA
Z Turbo 2TB PCIe-4x4 TLC SSD Module	Υ	Υ	38T75AA
Z Turbo 4TB 2280 PCIe-4x4 TLC M.2 SSD Module ⁶	Υ	Υ	5S496AA/AT
Z Turbo 4TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module ⁶	Υ	Υ	5S497AA/AT
Z Turbo 512GB PCIe-4x4 TLC Z4/Z6 Kit SSD	Υ	Υ	56Q73AA
Z Turbo 512GB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z4/Z6 Kit SSD	Υ	Υ	56Q74AA
Z Turbo 1TB PCIe-4x4 TLC Z4/Z6 Kit SSD	Υ	Υ	56Q75AA
Z Turbo 1TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z4/Z6 Kit SSD	Υ	Υ	5Z7E7AA
Z Turbo 2TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z4/Z6 Kit SSD	Υ	Υ	56Q77AA
Z Turbo 4TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z4/Z6 Kit SSD ⁶	Υ	Υ	5S4A1AA
HP Z Turbo Drive Dual Pro			
HP Z Turbo Drive Dual Pro PCIe-4x4 NVMe Carrier ³	Υ	Υ	56Q86AA
Intel® Virtual RAID on CPU (Intel® VROC) for NVMe			
Intel VROC NVMe SSD Premium Ctlr Module ⁵	N	Υ	3FJ81AA
Intel VROC NVMe SSD Standard Ctlr Module ⁴	N	Υ	3FJ80AA



Supported Components

Note 1: For internal bay install, HDD option kits require separate purchase of 74Y88AA HP Z4 HDD Cable Kit. For external bay install, HDD options kits require separate purchase of 74Y88AA HP Z4 HDD Cable Kit & NQ099AA HP Optical Bay HDD Mounting Bracket.

Note 2: Up to (4) 3.5-inch 7200 rpm SATA drives: 1TB, 2TB, 4TB, 8TB, 12TB; 48TB max

Note 3: Kit includes dual pro carrier and heatsink. Requires separate purchase of ZTurbo PCIe 4x4 M.2 SSD modules.

Note 4: Enables RAID 0, 1 & 10

Note 5: Enables RAID 0, 1 & 10 plus RAID 5 with write hole closure options

Note 6: Available in June 2023

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Graphics		Factory Configured	Option Kit	Option Kit Part Number	Supported # of cards
Graphics Cable	HP DisplayPort To VGA Adapter	N	Υ	AS615AA/AT	
Adapters	HP DisplayPort To VGA Adapter	N	Υ	F7W97AA	
	HP GFX Pwr Cbl CPU-8p to CPU-8p	Υ	Υ	6J6H7AA	
	HP GFX Pwr Cbl CPU-8p to x2 PCIe 8p(6+2)	Υ	Υ	6J6H8AA	
	HP DisplayPort to HDMI Adapter	Υ	Υ	2JA63AA	
	HP (Bulk 12) miniDP-to-DP Adapter Cables	N	Υ	2KW87A6	
	HP Single miniDP-to-DP Adapter Cable	Υ	Υ	2MY05AA	
	HP miniDP-to-DP Adapter (2-pack)	Υ	N		
	HP miniDP-to-DP Adapter (4-pack)	Υ	N		
	HP miniDP-to-DP Adapter (8-pack)	Υ	N		
	HP DisplayPort To DVI Adapter (Bulk 90)	N	Υ	FH973A6	
	NVIDIA NVLink 3-Slot Bridge	Υ	Υ	340L3AA	
	NVIDIA 3D Stereo Bracket	N	Υ	KOA25AA	
Ultra High-End	NVIDIA® RTX 6000 Ada 48GB ^{1,3,4}	Υ	Υ	79C23AA/AT	?
Graphics	NVIDIA® RTX A6000 48GB 1,3	Υ	Υ	2S6U3AA/AT	2
	NVIDIA® RTX A5000 24GB ¹	Υ	Υ	20X23AA/AT	2
	NVIDIA® Quadro® Sync II	N	Υ	1WT20AA	
High-End Graphics	NVIDIA® RTX A4500 20GB ¹	Υ	Υ	5S458AA/AT	2
	NVIDIA® RTX A4000 16GB ^{1,*}	Υ	Υ	20X24AA/AT	2
	NVIDIA® Long-Life RTX A4000E 16GB ^{1,4,*}	Υ	Υ	6H7J7AA/AT	2
	AMD® Radeon™ Pro W6800 32GB ^{1,3}	Υ	Υ	340K7AA	2
Midrange					_
Graphics	NVIDIA® RTX A2000 12GB ¹	Y	γ	5Z7D9AA/AT	2
	NVIDIA® Long-Life RTX A2000E 12GB ¹	Y	N		2
	NVIDIA® T1000 8GB ²	Y	Υ	5Z7D8AA/AT	2
	NVIDIA® Long-Life T1000E 8GB ²	Y	Υ	6V9V4AA/AT	2
	NVIDIA® T1000 4GB ²	Y	Υ	20X22AA/AT	2
	AMD® Radeon™ Pro W6600 8GB ¹	Y	Υ	340K5AA	2
	AMD® Radeon™ RX 6700XT 12GB ¹	Y	N		1
Entry	NVIDIA® T400 4GB ²	Y	Υ	5Z7E0AA/AT	2
	AMD® Radeon™ RX 6400 4GB	Y	Υ	6Q3U4AA/AT	1
	Intel Arc Pro A40 6GB ⁴	Y	Υ	6E3Y8AA	1



Supported Components

*Only supported with 1125W PSU

Note 1: Single or dual graphics configuration requires the HP Z4 Fan and Front Card Guide. If configured as an after-market option, a separate purchase of the HP Z4 Fan and Front Card Guide 56Q79AA is required. If factory configured, the fan and front card guide is included.

Note 2: Dual graphics configuration requires the HP Z4 Fan and Front Card Guide. If configured as an aftermarket option, a separate purchase of the HP Z4 Fan and Front Card Guide 56Q79AA is required. If factory configured, the fan and front card guide is included.

Note 3: Dual graphics configuration requires the HP Z4 PCIe Retainer with Fans. If configured as an aftermarket option, a separate purchase of the HP Z4 PCIe Retainer with Fans 56Q84AA is required. If factory configured, the PCIe retainer with fans is included.

Note 4: Available in June 2023

Memory		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	16GB (1x16GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	32GB (2x16GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	64GB (4x16GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	64GB (2x32GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	128GB (8x16GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		1
	128GB (4x32GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	256GB (8x32GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		1
	256GB (4x64GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		
	512GB (8x64GB) DDR5 4800 DIMM ECC REG Memory	Υ	N		1
	After Market Options				
	16GB DDR5 (1x16GB) 4800 DIMM ECC REG Memory	Υ	Υ	340K1AA	
	32GB DDR5 (1x32GB) 4800 DIMM ECC REG Memory	Υ	Υ	340K2AA	
	64GB DDR5 (1x64GB) 4800 DIMM ECC REG Memory	Υ	Υ	340K3AA	

NOTE 1: This memory configuration requires the 775W or 1125W PSU

Multimedia and		Factory		Option Kit
Audio Devices		Configured	Option Kit	Part Number
	HyperX Cloud Mix Wireless Gaming Headset	N	Υ	4P5K9AA
	HyperX Cloud Core Gaming Headset	N	Υ	4P4F2AA
	HyperX Cloud Flight Wireless Gaming Headset	N	Υ	4P5L4AA
	HyperX Cloud Stinger Core Gaming Headset	N	Υ	4P4F4AA
	HyperX SoloCast - USB Microphone	N	Υ	4P5P8AA
	Integrated Realtek ALC3205-CG Audio	Υ	N	

Factory Option Kit Configured Option Kit Part Number



Supported Components

Optical and
Removable
Storage

HP CRU QX428 Removable with 200mm Cable Frame/Carrier ^{1, 4}	Υ	Υ	56R11AA
HP DX175 Removable HDD Frame/Carrier ^{2, 4}	Υ	Υ	1ZX71AA
HP DX175 Removable HDD Spare Carrier ^{2, 4}	N	Υ	1ZX72AA
HP CRU Secure High Performance Storage Module with 2TB M.2 SSD ³	Υ	Υ	56Q87AA
HP CRU Secure High Performance Storage Module with 1TB M.2 SSD ³	Υ	Υ	56Q88AA
HP CRU Secure High Performance Storage Module with 512GB M.2 SSD ³	Υ	Υ	56Q89AA
HP 9.5mm Slim DVD-ROM Drive	Υ	Υ	K3R63AA
HP 9.5mm Slim BDXL Blu-Ray Writer Drive	Υ	Υ	K3R65AA
HP 9.5mm Slim SuperMulti DVD Writer	Υ	Υ	K3R64AA

Note 1: Requires separate purchase of HP CRU Secure High Performance Storage (SHIPS) Module(s).

Note 2: Only supports 4TB or lower capacity HDDs.

Note 3: HP CRU SHIPS Module Kit contains select M.2 SSD for install into a factory configured or after market option front removeable storage carrier (HP CRU QX428 Frame/Carrier).

Note 4: Planned to be available in June 2023

Networking and
Communications

	Factory Configured	Option Kit	Option Kit Part Number
HP 10GBase-T Flex Port	Υ	Υ	56Q71AA
HP 2.5GbE LAN Flex Port	Υ	Υ	169K0AA/AT
HP Flex 1GbE Single Port NIC	Υ	N	
HP 1GbE Fiber LC Single Flex Port	Υ	N	20J15AA
Intel® X550 10GBASE-T Dual Port NIC	Υ	Υ	1QL46AA
Intel® I225-T1 Single Port 2.5GbE PCIe NIC	Υ	Υ	406L9AA
Intel® Ethernet I350-T4 4-Port 1Gb NIC	N	Υ	W8X25AA
Intel® AX210 Wi-Fi 6 non-vPro +Bluetooth® 5.2 with Internal Antennae WLAN	N	N	
Allied Telesis AT-2914SX/LC-901 1GB LC Fiber NIC	Υ	Υ	1C7Q2AA
Allied Telesis AT-2911T/2-901 Dual Port 1GbE NIC	Υ	Υ	6E3Y9AA/AT
NVIDIA® Mellanox® ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC 1	Υ	Υ	436M8AA
Intel AX210 Wi-Fi 6E non-vPro + Bluetooth® 5.2 with External Antenna WLAN	Υ	Y	340L7AA

Note1: 3rd party transceivers sold separately. You must have a transceiver installed to connect this card to a network.

Racking and Physical Security		Factory Configured	Option Kit	Option Kit Part Number
	Z2 Mini/Z2 Tower/Z4/Z6 Depth Adjustable Fixed Rail Rack Kit	N	Υ	2A8Y5AA

Input Devices	Factory Configured	Option Kit	Option Kit Part Number
HP 320K Wired Keyboard	Υ	Υ	9SR37AA/ET/UT
HP 125 Wired Keyboard	Υ	Υ	266C9AA/ET/UT



Supported Components

HP 975 USB+BT Dual-Mode Wireless Keyboard	N	Υ	3Z726AA/ET/UT
HP 455 Programmable Wireless Keyboard	N	Υ	4R177AA/ET/UT/A6
HP Wired Desktop 320MK Mouse and Keyboard	N	Υ	9SR36AA/ET/UT
HP 655 Wireless Keyboard and Mouse Combo	N	Υ	4R009AA/ET/UT/A6
HP Wired 320M Mouse	Υ	Υ	9VA80AA/ET/UT
HP Creator 935 Black Wireless Mouse	N	Υ	1D0K8AA/ET/UT
HP 128 LSR Wired Mouse	Υ	Υ	265D9AA/ET/UT
HP 125 Wired Mouse	N	Υ	265A9AA/ET/UT
HP Business Slim Smartcard Keyboard	Υ	Υ	Z9H48AA/AT

NOTE: Keyboard and Mouse are optional or add on features.

Other Hardware		Factory Configured	Option Kit	Option Kit Part Number
	HP Z4 Fan and Front Card Guide Kit⁵	Υ	Υ	56Q79AA
	HP Z4 Memory Cooling Solution ⁴	Υ	Υ	56Q81AA
	HP Z4 PCIe Retainer with Fans⁵	Υ	Υ	56Q84AA
	HP 2.5in to 3.5in HDD Adapter Kit	N	Υ	J5T63AA
	HP Internal Serial+PS/2 Port	Υ	Υ	56Q78AA
	HP Serial Port Flex IO v3	Υ	Υ	13L56AA/AT
	HP Dual USB-A 3.2 Gen1 Flex 2020	Υ	Υ	141J8AA/AT
	HP USB-C 3.2 Gen2 Alt Flex Port 2020	Υ	Υ	141K6AA/AT
	HP Dual TBT4 PCIe x4 Low Profile Card ⁶	Υ	Υ	340L1AA
	HP USB 2.0 Type-A Port Adapter Kit ¹	Υ	Υ	79C24AA
	HP Type-C SuperSpeed USB 20Gbps Front IO v2 Premium Module	Υ	Υ	TBD
	HP 2.5in HDD/SSD 2-in-1 Optical Bay Bracket	N	Υ	K4T74AA
	HP Z4 HDD Cable Kit ²	N	Υ	74Y88AA
	HP Optical Bay HDD Mounting Bracket ³	N	Υ	NQ099AA
	HP Z4 Dust Filter	Υ	Υ	3DY47AA
	HP SD 4 Card Reader Zx G4	Υ	Υ	2VK54AA

Note 1: The HP USB 2.0 Type-A Port Adapter Kit 79C24AA has a single USB 2.0 type A connector.

Note 2: HP Z4 HDD Cable Kit 74Y88AA is required as a separate purchase for HDD option kit install into an internal bay. For external bay install, a separate purchase of 74Y88AA HP Z4 HDD Cable Kit & NQ099AA HP Optical Bay HDD Mounting Bracket is required.

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Note 3: NQ099AA HP Optical Bay HDD Mounting Bracket is required as a separate purchase for HDD option kits installed into an external bay.

Note 4: HP Z4 Memory Cooling Solution 56Q81AA is required as a separate purchase for after-market memory configurations using 32GB Registered DIMMs or greater. If configured from the factory, configurations using 32GB Registered DIMMs or greater will include a memory cooling solution.

Note 5: HP Z4 Fan and Front Card Guide 56Q79AA and HP Z4 PCIe Retainer with Fans 56Q84AA are required for specific graphics configurations (see Graphics section).

Note 6: Available in June 2023

HP C13 1.83m Power Cord Kit

Software Factory Support
Configured Option Kit Notes



6Z1T9AA

Supported Components

Data Science Stack Y N 1
WSL2/Ubuntu Data Science Stack Y N 1
Microsoft Office Home and Business Japan 2021 Y N

Note 1: Only available with Ubuntu and NVIDIA® graphics

Operating Systems Windows 11 Pro for Workstations^{1,2}

Windows 11 Pro for Workstations (preinstalled with Windows 10 Pro for Workstations Downgrade) ^{1,2,3}
Ubuntu 22.04 LTS⁴
HP Linux®-ready

¹ Windows Enterprise sold separately and requires that customer have an enterprise license from Microsoft. ² Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

³This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

⁴ Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply and additional requirements may apply over time for updates.

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282



Supported Components

HP BIOS

Key features of the HP BIOS include:

- Deployment and manageability HP BIOS provides several technologies that help integrate
 the HP Z8 Fury G5 Workstation into the enterprise, such as PXE, remote recovery, remote
 configuration, remote control, and BIOS (F10) Setup support for 15 languages.
- Network firmware updates –Update your BIOS via the cloud or standardize on a BIOS version hosted on an Enterprise network.
- Stability HP BIOS supports the HP stable product roadmap by releasing only critical BIOS changes to the factory and advanced change notification.
- Class 3 UEFI specification version 2.7
- Absolute Persistence agent For tracking and tracing services, available in select countries, separate software and purchase of a subscription is required.
- Thermal and power management The HP BIOS provides and enables thermal and power management technologies so component temperatures are managed for high reliability and to assist in operating the HP Workstation computer in any enterprise environment.
- Acoustic performance Industry leading acoustic emissions across the range of operating conditions.
- Serviceability HP BIOS provides diagnostic and detailed service information.
- Upgrades and recovery HP BIOS provides numerous ways to upgrade HP Workstation computers, including BIOS updates from within Windows (HP Firmware Update and Recovery), Capsule update, HP Client Manager, and fail-safe recovery. In addition, the HP BIOS Configuration Utility enables replication of BIOS settings within Windows while the Replicated Setup feature provides the same capability within BIOS (F10) Setup. The BIOS Configuration Utility is available from the HP support website.
- HP BIOS uses PKI signing of the BIOS for trusted BIOS upgrades and recovery. Additional HP BIOS Features:
 - Power-On password Helps prevent an unauthorized user from powering on the system.
 - Administrator password Also known as the BIOS Setup password, this helps prevent unauthorized changes to the system configuration. If the administrator password is not known, the BIOS cannot be updated and changes cannot be made to BIOS settings using BIOS Setup or under the OS.
 - S4/S5 Maximum Power Savings setting supports EU Lot6 requirement and allows the computer to power down below 0.5W in S4/S5 (when turned off). When S4/S5 Maximum Power Savings feature is enabled below features are turned off:
 - Power to expansion connectors / slots
 - Most Wake events other than power buttons and WOL (Wake on LAN supported by embedded Lan controller under S4/S5 Maximum Power Saving Enabled)
 - USB charging ports

HP Sure Start Gen7

- BIOS Integrity checking Sure Start protection ensures that only trusted BIOS code is
 executed and not rootkits, viruses and malware. Verification is done upon boot up, shutdown
 and while the system is on.
- Sure Start is set by default to automatically repair the BIOS if corrupted or compromised but is
 policy driven for better manageability. Start is set by default to automatically repair the BIOS
 if corrupted or compromised but is policy driven for better manageability.
- Protecting beyond BIOS Integrity checking and repair is extended to other data that should be protected such as network configuration parameters, platform specific information (i.e. system IDs), secure boot credentials, and other code the system needs to boot.
- Audit enabled System Audit via Sure Start Event Logs capture data such as incident, repair date and time for troubleshooting and investigating.



Supported Components

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Software

HP Support Assistant 14

HP Image Assistant

HP Desktop Support Utility

HP Documentation

HP Notifications

HP PC Hardware Diagnostics UEFI

HP PC Hardware Diagnostics Windows

HP Performance Advisor¹

myHP

HP Easy Clean²⁰

HP Smart Health²¹

WSL/Ubuntu Data Science Stack

HP Privacy Settings

Touchpoint Customizer for Commercial

Manageability Features

HP Driver Packs²

HP UWP Pack

HP System Software Manager (SSM)

HP Manageability Integration Kit Gen43

HP Smart Support⁵

HP Client Catalog (download)

HP Image Assistant (download)

HP Cloud Recovery

HP Client Management Script Library (download)

HP BIOSphere Gen6 13

Client Security Software

HP Client Security Suite Gen7⁴ including: (including Credential Manager, HP Password Manager⁶, HP Spare Key)

HP Power On Authentication

Microsoft Defender⁷

Security Management

HP Secure Erase 16

HP Wolf Pro Security Edition (optional) 18

HP Wolf Security for Business²² Includes:

HP Sure Click¹¹

HP Sure Sense¹²

HP Sure Run Gen59

HP Sure Recover Gen4 10

HP Sure Start Gen78

HP Tamper Lock

HP Sure Admin 17

HP Client Security Manager Gen 74

² HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.



¹ HP Performance Advisor Software - HP Performance Advisor is ready to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at: http://hp.com/PerformanceAdvisor

Supported Components

- ³ HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html
- ⁴ HP Client Security Manager Gen7 requires Windows and is available on the select HP PCs.
- ⁵ HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights and is available preinstalled on select products, thru HP Factory Configuration Services; or it can be downloaded. For more information about how to enable HP Smart Support or for download, please visit http://www.hp.com/smart-support.
- ⁶ HP Password Manager requires Internet Explorer or Chrome or FireFox. Some websites and applications may not be supported. User may need to enable or allow the add-on / extension in the internet browser.
- ⁷ Microsoft Defender Opt in and internet connection required for updates.
- ⁸ HP Sure Start Gen 7 is available on select HP PCs and workstations. See product specifications for availability.
- ⁹ HP Sure Run Gen5 is available on select Windows 11 based HP Pro, Elite and Workstation PCs with select Intel® or AMD processors
- ¹⁰ HP Sure Recover Gen4 is available on select HP PCs and requires Windows 10 and an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module
- 11 HP Sure Click requires Windows 10 Pro or higher or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details.
- ¹² HP Sure Sense requires Windows 11 Pro or Enterprise and supports Microsoft Internet Explorer, Google Chrome™, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.
- ¹³ HP BIOSphere Gen6 features may vary depending on the platform and configurations.
- ¹⁴ HP Support Assistant requires Windows and Internet access.
- ¹⁶ Secure Erase For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane.
- ¹⁷ HP Sure Admin requires Windows 11, HP BIOS, HP Manageability Integration Kit from
- http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.
- ¹⁸ HP Wolf Pro Security Edition is available preloaded on select SKUs and, depending on the HP product purchased, includes a paid 1-year or 3-year license. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software End-User license Agreement (EULA) that can be found at: https://support.hp.com/us-
- en/document/ish_3875769-3873014-16 as that EULA is modified by the following: "7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition (HP Sure Sense Pro and HP Sure Click Pro) is effective upon activation and will continue for either a twelve (12) month or thirty-six (36) month license term ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support.
- ²⁰ HP Easy Clean requires Windows 10 RS3 and higher and will disable the keyboard, touchscreen, and clickpad only. Ports are not disabled. See user guide for cleaning instructions.
- ²¹ HP Smart Health automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights and is available preinstalled on select products, thru HP Factory Configuration Services; or it can be downloaded. For more information about how to enable HP Smart Support or for download, please visit http://www.hp.com/smart-support.
- ²² HP Wolf Security for Business requires Windows 10 or higher, includes various HP security features and is available on HP Pro, Elite, RPOS and Workstation products. See product details for included security features



System Technical Specifications

System Board

System Board Form

Approximately 284.48mm x 297.18mm (11.2x11.9 inches).

Factor

Processor Socket Single LGA-4677

CPU Bus Speed DMI Gen4 x 8 lanes

Chipset Intel W790 Alder Lake – WS PCH

Super I/O Controller Nuvoton SIO21

Memory Expansion Slots 8 DDR5 memory slots

Memory Type Supported DDR5, RDIMM (Registered) ECC

Memory Modes Non- Interleaved for single channel. Interleaved when multiple channels are populated

Memory Speed Supported 4800MT/s for 1DPC and 4400MHz for 2DPC

Memory ProtectionECC on dataMaximum Memory512GB

Memory Configuration 16GB, 32GB and 64GB RDIMMs are supported.

(Supported) (64GB RDIMM cannot be mixed with other module capacities in the same system)

NVDIMM Memory No.

PCI Express Connectors Standard PCIe Slots

1 PCI Express Gen5 slot x16 mechanical/ x16 electrical (full height, full length)
 2 PCI Express Gen4 slot x16 mechanical/ x16 electrical (full height, full length)
 2 PCI Express Gen4 slot x4 mechanical/ x4 electrical (full height, half length)

M.2 Slots:

• 2 PCI Express Gen4 slot x4.

Other PCIe Connections

• 1 Front NVMe Storage (SlimSAS PCIe Gen4 x8) (supports two x4 M.2 devices via QX428)

Supported Drive Interfaces

SATA Number of SATA ports: 5

Intel® SATA controller: primary SATA

Integrated RAID On-board RAID Support

Intel® VROC® SATA RAID 0, 1, 5, and 10 supported on Windows 10 and

11. RHEL 8.6 and later. SLE 15 SP4 and later

Intel® VROC® NVMe RAID 0, 1, 5, and 10 supported with presence of appropriate VROC upgrade module (after-market kits) on Windows 10

and 11, RHEL 8.6 and later, SLE 15 SP4 and later

Factory Configured RAID: None

Integrated Graphics No

Network Controller WGI219LM.

WGI219LMLOM provides Management capabilities: WOL, PXE 2.1,

DASH 1.1 and AMT

External SATA (eSATA) No

Serial 1 internal header (requires optional Serial Port Adapter Kit)

2nd Serial No **HD Integrated Audio** Yes

USB Connector(s) Front Front I/O Entry:

4 USB 3.1 Gen1 Type-A (left-most port supports Battery Charging 1.2)

Front I/O Premium:

2x USB 3.2 Gen2x2 Type-C™ (Power Delivery 3.0)



System Technical Specifications

2x USB 3.1 Gen1 Type-A (left-most port supports Battery Charging 1.2)

• USB Type-C Ports provide 3 Amps @ 5 Volts

Charging USB Type-A port provides 1.5 Amps @ 5 Volts
Standard USB Type-A Ports provide 900mA @ 5 Volts

Rear 4x USB 3.1 Gen1 Type-A with USB hub and 2x USB 3.2 Gen 1 Type-A

without hub.

(Optional: 2x USB 3.0 Type-A (optional via Flex module) or 1x USB 3.1

Gen2 Type-C charging port (optional via Flex module).

Internal 1 USB 3.2 Gen1 header, with a single 12-pin shrouded connector. This

header supports a USB Media Card reader.

1 USB 2.0 single port header 1 USB 2.0 dual port header.

Flash ROM Yes CPU Fan Header Yes

Memory Fan Header Yes (dual header)

Chassis Fan Header 1 front, one rear and one Aux Fan Header (dual)

Front PCI Fan Header Yes (connects to AUX fan header)

Front Control Yes

Panel/Speaker Header

Integrated Trusted

CMOS Battery Holder - Yes

Lithium

Integrated TPM 2.0.

Platform Module Convertible to FIPS 140-2 Certified Mode through firmware v15.21.

The TPM module is disabled where restricted by law.

Power Supply Headers Yes
Power Switch, Power LED Yes
& Hard Drive LED Header
Clear Password Jumper Yes

Keyboard/Mouse USB and PS/2 (option)

¹Maximum memory capacities assume 64-bit operating systems, such as Genuine Windows® 11 Professional 64 bit, Red Hat Linux 64-bit.

²M.2 storage supports compatible devices up to 80mm

System Technical Specifications

System Configuratio		I							
Example Configuration	Processor Info		w3-2425 6C 3		80W				
#1	Memory Info	16GB DDR5 (1	x16GB) RegRA	AM					
	Graphics Info	1xNvidia T100	1xNvidia T1000						
	Disks/Optical/Floppy	1x Internal 4TB M.2 + 1xDVDRW SATA							
	PSU	525W							
	Other	N/A							
Energy Consumption		115	VAC	230	VAC	100	VAC		
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled		
	Windows Idle (S0)	58.901	57.056	59.256	57.246	58.889	57.005		
	Windows Busy Typ (S0)	201	1.08	198	3.26	200).56		
	Windows Busy Max (S0)	513	.451	206	.345	205	.432		
	Sleep (S3)	3.570	3.489	3.577	3.495	3.569	3.487		
	Off (S5)	2.100	2.097	2.112	2.110	2.095	2.090		
	Zero Power Mode (EuP)	0.1	153	0.1	193	0.1	52		
Heat Dissipation		115 VAC		230 VAC		100 VAC			
Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled		
	Windows Idle (S0)	200.97	194.67	202.18	195.32	200.988	194.558		
	Windows Busy Typ (S0)	686.08		676	5.46	684.31			
	Windows Busy Max (S0)	728.508		704.255		701.139			
	Sleep (S3)	12.180	11.904	12.204	11.924	12.177	11.897		
	Off (S5)	7.165	7.154	7.206	7.199	7.148	7.131		
	Zero Power Mode (EuP)	0.5	522	0.6	559	0.5	18		
Example Configuration	Processor Info	1x Intel Xeon	w3-2435 8C 3	.1GHz 4800 16	55W				
#2	Memory Info	32GB DDR5 (2	2x16GB) RegRA	λM					
	Graphics Info	1xNVIDIA Qua	dro A2000						
	Disks/Optical/Floppy	1x 1TB SATA I	HDD + 1xInterr	nal 4TB M.2 + 1	xDVDRW SATA	<u> </u>			
	PSU	775W							
	Other	N/A							
Energy Consumption		115	VAC	230	VAC	100	VAC		
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled		
	Windows Idle (S0)	66.084	65.053	66.356	65.226	65.852	64.789		
	Windows Busy Typ (S0)	258	3.55	254	1.89	257	'.86		
	Windows Busy Max (S0)	<u> </u>	9.94	1	5.59	1	3.95		
	Sleep (S3)	3.916	3.808	3.925	3.812	3.912	3.801		
	Off (S5)	22.36	2.216	2.248	2.224	2.234	2.213		
	Zero Power Mode (EuP)	-	202		241	1	201		
	1 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2	1		1		1 31-			
		115	VAC	230	VAC	100	VAC		



System Technical Specifications

		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	225.47	221.96	226.40	222.55	224.687	221.060
Heat Dissipation	Windows Busy Typ (S0)	882	2.17	869	9.68	879	.81
(Btu/hr)	Windows Busy Max (S0)	955	5.15	940).31	951	.77
	Sleep (S3)	13.361	12.992	13.392	13.006	13.347	12.969
	Off (S5)	7.629	7.560	7.670	7.588	7.622	7.550
	Zero Power Mode (EuP)	0.6	89	0.8	322	0.6	85
Example Configuration	Processor Info	1x Intel Xeon	w5-2455X 120	3.2GHz 4800	200W		
#3	Memory Info	64GB DDR5 (4	x16GB) RegRA	М			
	Graphics Info	1xNvidia Quad	dro A4000				
	Disks/Optical/Floppy	2x 1TB SATA I	HDD + 1xIntern	al 4TB M.2 + 1	xDVDRW SATA	1	
1	PSU	1125W					
	Other	N/A					

Energy Consumption		115	115 VAC		230 VAC		100 VAC	
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
	Windows Idle (S0)	82.533	79.464	82.821	79.725	82.412	79.325	
	Windows Busy Typ (S0)	400	0.06	396	5.25	399.23		
	Windows Busy Max (S0)	411	.532	403	.423	404	.356	
	Sleep (S3)	4.403	4.332	4.409	4.335	4.400	4.328	
	Off (S5)	2.411	2.395	2.418	2.400	2.406	2.390	
	Zero Power Mode (EuP)	0.2	236	0.2	278	0.2	234	

Heat Dissipation		115 VAC		230 VAC		100 VAC	
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	281.60	271.13	282.58	272.02	281.18	270.65
	Windows Busy Typ (S0)	136	5.00	135	2.00	136	2.17
	Windows Busy Max (S0)	1404	1.558	1376	5.883	1380	0.067
	Sleep (S3)	15.023	14.780	15.043	14.791	15.012	14.767
	Off (S5)	8.226	8.171	8.250	8.177	8.209	8.154
	Zero Power Mode (EuP)	0.0	305	0.9	948	0.7	798

Example Configuration	Processor Info	1x Intel w7-2495X 24C 2.5GHz 4800 225W
#4	Memory Info	128GB DDR5 (4x32GB) RegRAM
	Graphics Info	1xNVIDIA Quadro A6000
	Disks/Optical/Floppy	2x 4TB 7200 RPM SATA + 2x Internal 4TB M.2 + 1xDVDRW SATA
	PSU	1125W
	Other	N/A

Energy Consumption		115	VAC	230	VAC	100	VAC
(Watts)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows dle (S0)	596.25	592.56	595.23	596.25	592.56	595.23



System Technical Specifications

Windows Busy Typ	(S0) 60	8.784	600.	.412	601	314
Windows Busy Max	(S0) 6	.080	5.9	36	6.0	85
Sleep (S3)	2.361	2.356	2.370	2.361	2.356	2.370
Off (S5)	0.231	0.279	0.230	0.231	0.279	0.230
Zero Power Mode (E	iuP) 59	6.25	592	56	595	.23

Heat Dissipation		115	VAC	230 VAC		100 VAC	
(Btu/hr)		LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
	Windows Idle (S0)	308.25	298.73	309.32	299.65	307.88	298.33
	Windows Busy Typ (S0)	203	4.40	302	1.81	203	0.92
	Windows Busy Max (S0)	2077	7.779	2049	9.206	2052	2.285
	Sleep (S3)	20.744	20.253	20.762	20.267	20.727	20.233
	Off (S5)	8.055	8.038	8.086	8.067	8.048	8.025
	Zero Power Mode (EuP)	0.7	788	0.9	951	0.7	'84

NOTE: The numbers in this table are from actual measurements on a single system. There will be some variation from unit to unit.

NOTE: The busy power number and associated BTU/hr number for each configuration will be a strong function of the actual application software run on the system. There can be a great deal of variation in this number.

NOTE: The Power Supply Efficiency report may be found at the following links:

https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2

System Technical Specifications

Operating Voltage Range 90-269 VAC **Rated Voltage Range** 100-240 VAC **Rated Line Frequency** 50-60 Hz **Operating Line Frequency** 47-66 Hz

Range

ENERGY STAR® certified

(Config Dependent)

Yes

Yes

Yes

Yes

Yes, with Wake-on-LAN disabled: <1W in S5 - Power Off

CECP Compliant @ 220V

FEMP Standby Power

Compliant

Built-in Self Test (BIST)

LED

Surge Tolerant Full Ranging Power Supply

(withstands power surges

up to 2000V)

Hood Lock Header Yes ErP Lot 6- Tier 1 Yes Compliance @ 230V (<1W

in S5 - Power Off)

ErP Lot 6- Tier 2 Yes

Compliance @ 230V (<0.5W in S5 - Power Off)

System Configuration	Processor Info	1x Intel Xeon w3-2425 6C 3.0GHz 4800 130W				
(Entry level)	Memory Info	32GB (2x 16GB) DDR5 4800MHz RDIMI	M			
	Graphics Info	1xNVIDIA Quadro A2000				
	Disks/Optical	1x512GB SSD + 1xInternal 1TB M.2+ 1	xDVDRW SATA			
	Power Supply	525W				
Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)			
	Idle	3.4	15			
	Hard drive Operating (Drive Random Seek)	3.4	15			
	Active mode	3.3	15			
System Configuration	Processor Info	1x Intel Xeon w5-2455X 12C 3.2GHz 4	800 200W			
(Mid-level)	Memory Info	128GB (8*16GB) DDR5 4800MHz RDIM	M			
	Graphics Info	1xNVIDIA Quadro A4000				
	Disks/Optical	1x1TB HDD + 2xInternal 1TB M.2 SSD	+ 1xDVDRW SATA			
	Power Supply	775W				
Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)			
	Idle	3.4	16			
	Hard drive Operating (Drive Random Seek)	3.4 16				



System Technical Specifications

	Active mode	3.4	16	
System Configuration (High-end)	Processor Info	1x Intel Xeon w7-2495X 24C 2.5GHz 4800 225W		
	Memory Info	512GB (8x64GB) DDR5 4800MHz RDIMM		
	Graphics Info	2xNVIDIA Quadro A6000		
	Disks/Optical	2x4TB HDD + 2xInternal 4TB M.2 SSD + 1xDVDRW SATA		
	Power Supply	1125W		
Declared Noise Emissions		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)	
	Idle	3.7	21	
	Hard drive Operating (Drive Random Seek)	3.8	21	
	Active mode	4.0	23	

Environmental Requirements

Temperature Operating: 5° to 35° C (40° to 95° F)

Non-operating: -40° to 60° C (-40° to 140° F)

Humidity Operating: 8% to 85% RH, non-condensing

Non-operating: 8% to 90% RH, non-condensing

Maximum Altitude Operating: 3,048 m (10,000 feet)

Non-operating: 9,144 m (30,000 feet)

Dynamic Shock

Operating: ½-sine: 40g, 2-3ms (~62 cm/sec) Non-operating: ½-sine: 160 cm/s, 2-3ms (~105g)

square: 422 cm/s, 20g

NOTE: Values represent individual shock events and do not indicate

repetitive shock events

Vibration

Operating random: 0.5g (rms), 5-300 Hz, up to $0.0025g^2/Hz$ Non-operating random: 2.0g (rms), 5-500 Hz, up to $0.0150\,g^2/Hz$

NOTE: Values do not indicate continuous vibration.

Cooling Above 1524 m (5,000 feet) altitude, the maximum operating temperature

is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation,

up to 3048 m (10,000 feet)

System Technical Specifications

Physical Security and Serviceability

Access Panel Tool-less

Includes system board and memory information

Optical Drive Tool-less, Optical Drive requires a 5.25" bay carrier

Hard Drives Tool-less **Expansion Cards** Tool-less

Processor Socket Screw-in processor coolers

Blue User Touch Points Yes, on tool-less internal chassis mechanisms

Color-coordinated Cables Yes

and Connectors

Tool-less Memory **System Board** Screw-in **Dual Color Power and HD** Yes **LED on Front of Computer**

Dual Function Front

Power Switch

Yes, causes a fail-safe power off when held for 4 seconds

Padlock Support Yes (optional): Locks side cover and secures chassis from theft 7.0 mm (0.2756 in) diameter padlock

loop at rear of system

Yes. Kensington Cable Lock (optional): Locks side cover and secures chassis from theft 3 mm x 7 mm **Cable Lock Support**

slot at rear of system

Universal Chassis Clamp

Lock Support

Yes (optional): Locks side cover and locks cables to chassis. Secures chassis from theft and allows multiple units to be chained together when used with optional cable with threaded feature at rear of

svstem

Chassis Interlock Sensor Yes

Sensor detects when the access panel has been removed. The access panel must be installed for the

system to power ON. Removal of the access panel during operation will power OFF the system.

Solenoid Lock and Hood

Sensor

Yes (optional)

The Solenoid Hood Lock eliminates the need for a physical key by making the chassis lockable through software and a password. You can also lock and unlock the chassis remotely over the network. The

Sensor Kit detects when the access panel has been removed

Rear Port Control Cover

Serial. USB. Audio.

Network, Enable/Disable

Port Control

Power-On Password Yes

Yes, prevents an unauthorized person from changing the workstation configuration. Setup Password

3.3V Aux Power LED on

System PCA

None

No

Yes

NIC LEDs (integrated) (Green & Amber)

Yes

CPUs and Heatsinks A torx driver (T30) is needed to remove the processor heatsink. CPU attached to heatsink via tool-less

Power Supply Diagnostic Yes

LED

Front Power Button Yes **Front Power LED** Yes Front Hard Drive Activity Yes

Front ODD Activity LED Yes. on device



System Technical Specifications

Internal Speaker Yes System/Emergency ROM Yes

Flash Recovery

Cooling Solutions Air cooled forced convection

Power Supply Fans 80 mm x 80 mm x 25 mm (non-serviceable)

CPU Heatsink Fan 108 mm x 108 mm x 25 mm **Chassis Fan** Rear: 120 mm x 120mm x 25 mm

Front (optional): 92 mm x 92 mm x 25 mm

PCIe Retainer (optional based on configuration): Dual 80 mm x 80 mm x 20 mm Dual 60 mm x 60 mm x 25 mm Blindmate (optional based on configuration)

Memory Heatsink Fan Access Panel Kev Lock Yes, side panel barrel keylock (optional from the factory only)

ACPI-Ready Hardware Advanced Configuration and Power Management Interface (ACPI).

• Allows the system to wake from a low power mode.

• Controls system power consumption, making it possible to place individual cards and peripherals in a

low-power or powered-off state without affecting other elements of the system.

Integrated Chassis

Handles

Yes, front handle and dedicated rear recess

Power Supply Requires T15 Torx or flat blade screwdriver

Yes, rear (all), middle (all), front (full-length cards with extender, using Fan and Front Card **PCI Card Retention**

Guide Kit)

Flash ROM Yes **Diagnostic Power Switch** Yes

LED on board

Clear Password Jumper Yes **Clear CMOS Button** Yes **CMOS Battery Holder** Yes **DIMM Connectors** Yes

Service, Support, and Warranty

On-site Warranty and Service¹: Three-years, limited warranty and service offering delivers on-site, next business-day² service for parts and labor and includes free telephone support³ 8am - 5pm. Global coverage² ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering, 24/7 operation will not void the HP warranty. Storage devices are not covered under warranty for 24/7 operation except for Enterprise class HDDs.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider. and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may

NOTE 3: Technical telephone support applies only to HP-configured. HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries.

HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/lookuptool. Service levels and response times for HP Care Packs may vary depending on your geographic location.

Certification and Compliance

Environmental Sustainability questions concerning:

- Ecolabels (EPEAT, TCO, etc.)
- ENERGY STAR, California Energy Commission (CEC)



System Technical Specifications

- Compliance with Environmental legislation (EU ErP, China CECP, EU RoHS and other countries)
- Supply Chain Social Environmental Responsibility (SER) (conflict minerals; human rights, etc.)
- Product specific environmental features (material content, packaging content, recycled content, etc.)
- China Energy Label (CEL)

Please contact sustainability@hp.com

For country specific Regulatory Compliance approval documents or Regulatory and Safety questions concerning:

- Declarations of Conformity (for self-service, go to https://www.hp.com/uken/certifications/technical/regulations-certificates.html?jumpid=ex_r135_uk/en/any/corp/hpukmu chev/certificates)
- **GS** Certificates
- Product Safety Certificates (UL, CB, BIS, etc.)
- EMC Certificates, Declarations of Conformity, or Certificates of Conformity (CE, FCC, ICES, etc.)
- **CCC** Certificates
- **Ergonomics**

Please contact techregshelp@hp.com

BIOS

PCIe 5.0 Support Full BIOS support for PCI Express through industry standard interfaces. Supported speeds and slot

information vary.

ATA/ATAPI AT Attachment 6 with Packet Interface (ATA/ATAPI-6). Revision 3b

WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is **WMI Support**

fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM)

and WBEM specifications.

BIOS Power On Users can define a specific date and time for the system to power on.

ROM Based Computer Setup Utility (F10)

Review and customize system configuration settings controlled by the BIOS.

System/Emergency ROM Recovers system BIOS in corrupted Flash ROM.

Flash Recovery with

Video

Replicated Setup Saves BIOS settings to USB flash device in human readable file (HpSetup.txt).

BiosConfigurationUtility.exe utility can then replicate these settings on machines being deployed

without entering Computer Configuration Utility (F10 Setup).

SMBIOS System Management BIOS Reference Specification, Version 3.2

Boot Control

Disables the ability to boot from removable media on supported devices. Alerts management console if memory is removed or changed.

Memory Change Alert

Thermal Alert Monitors the temperature state within the chassis. Three modes:

NORMAL - normal temperature ranges.

ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid

shutdown or provide for a smoother system shutdown.

SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer

without warning before hardware component damage occurs.

Remote ROM Flash Provides secure, fail-safe ROM image management from a central network console.

ACPI (Advanced Allows the system to enter and resume from low power modes (sleep states). Configuration and Power Enables an operating system to control system power consumption based on the dynamic workload.

Makes it possible to place individual cards and peripherals in a low-power or powered-off state without Management Interface)

affecting other elements of the system.

Supports ACPI 6.0 for full compatibility with 64-bit operating systems.

A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen. Ownership Tag

System Technical Specifications

Remote Wakeup/Remote System administrators can power on, restart, and power off a client computer from a remote location.

Shutdown

Instantly Available PC (Suspend to RAM - ACPI Allows for very low power consumption with quick resume time.

sleep state S3)

Remote System Installation via F12 (PXE 2.1) (Remote Boot from

Allows a new or existing system to boot over the network and download software, including the operating system.

Server)

ROM revision levels Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is

available through an industry standard interface (SMBIOS and WMI) so that management SW

applications can use and report this information.

System board revision

level Start-up Diagnostics Allows management SW to read revision level of the system board. Revision level is digitally encoded into the HW and cannot be modified. Assesses system health at boot time with selectable levels of testing.

(Power-on Self-Test) Auto Setup when new

hardware installed

System automatically detects addition of new hardware.

Keyboard-less Operation The system can be booted without a keyboard.

Common BIOS image supports System Configuration Utility (F10 Setup) menus in 15 languages with **Localized ROM Setup**

local keyboard mappings.

The user or MIS to set a unique tag string in non-volatile memory. **Asset Tag**

Per-slot Control Allows I/O slot parameters (option ROM enable/disable, bifurcation, speed) to be configured

individually.

Adaptive Cooling

Pre-boot Diagnostics

(Pre-video) critical errors are reported via beeps and blinks on the power LED.

Control parameters are set according to detected hardware configuration for optimal acoustics.

UEFI Specification

Revision

2.7

Advanced Configuration and Power Management Interface, Version 6.0 ACPI

CD Boot "El Torito" Bootable CD-ROM Format Specification Version 1.0

Enhanced Host Controller Interface for Universal Serial Bus. Revision 1.0 **EHCI PCI Express**

PCI Express Base Specification, Revision 2.0 PCI Express Base Specification, Revision 3.0 PCI Express Base Specification, Revision 4.0 PCI Express Base Specification, Revision 5.0

SATA Serial ATA Specification, Revision 1.0a

> Serial ATA 3 Gb/s: Serial ATA Specification, Revision 2.5 Serial ATA 6 Gb/s: Serial ATA Specification, Revision 3.0

SPD JEDEC JESD300-5

TPM Trusted Computing Group TPM Specification Version 2.0 (Infineon SLB 9672).

Common Criteria EAL4+ certified.

FIPS 140-2 Certification

TCG TPM Certified products list:

http://www.trustedcomputinggroup.org/certification/tpm-certified-products/

UHCI Universal Host Controller Interface Design Guide, Revision 1.1

USB Universal Serial Bus Revision 1.1 Specification

Universal Serial Bus Revision 2.0 Specification Universal Serial Bus Revision 3.1 Specification Universal Serial Bus Revision 3.2 Specification USB Battery Charging specification, Revision 1.2 USB Power Delivery specification Revision 3.0

System Management BIOS Reference Specification, Version 3.2 **SMBIOS**

System Technical Specifications

Social and Environmental Responsibility

& Declarations

Eco-Label Certifications This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- ENERGY STAR® (energy-saving features available on selected configurations-Windows only)
- US Federal Energy Management Program (FEMP)
- EPEAT^[] Gold registered worldwide
- TCO Certified
- China Energy Conservation Program (CECP)

Sustainable Impact **Specifications**

- Ocean-bound plastic in system fans
- 40% post-consumer recycled plastic
- Contains 10% post-industrial recycled metal
- Internal Power Supply 90% efficient

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".

Energy Consumption (in accordance with US

ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz
Normal Operation (Sort idle)	67.15 W	67.86 W
Normal Operation (Long idle)	64.93 W	64.85 W
Sleep	3.92 W	4.04 W
Off	2.23 W	2.30 W

NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family . HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz
Normal Operation (Short idle)	228.98 BTU/hr	231.40 BTU/hr
Normal Operation (Long idle)	221.41 BTU/hr	221.14 BTU/hr
Sleep	13.37 BTU/hr	13.78 BTU/hr
Off	7.60 BTU/hr	7.84 BTU/hr

*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions /:-------

Sound Power	Sound Pressure
(L _{wAd} , bels)	(L _{pAm} , decibels)
3.4	15
3.4	15
3.3	15
	(L _{WAd} , bels) 3.4 3.4



System Technical Specifications

Longevity and Upgrading

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:

- 3 USB ports
- 1 PC card slot (type I/II)
- 1 ExpressCard/54 slot
- 1 IEEE 1394 Port
- 2 SODIMM memory slots
- Optional expansion base docking station
- 1 multi-bay II storage port
- Interchangeable HDD

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

Batteries

This battery in this product complies with EU Directive 2006/66/EC

Battery size: CR2032 (coin cell) Battery type: Lithium Metal

The battery in this product does not contain:

- · Mercury greater than5ppm by weight
- Cadmium greater than 10ppm by weight
- Lead greater than 40 ppm by weight

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product is 94.8% recycle-able when properly disposed of at end of life.

Packaging Materials

External: PAPER/Corrugated At least 35% Recycled

PAPER/Molded Pulp 100% Recycled

Internal: PLASTIC/Polvethylene low 80% Recycled

density - LDPE

The corrugated paper packaging materials contains at least 62.5% recycled content.

RoHS Compliance

HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.

We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.

We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.



3.4

System Technical Specifications

To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these quidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.



System Technical Specifications

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP, Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

footnotes

- Percentage of ocean-bound plastic contained in each component varies by product
- Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.
- External power supplies, WWAN modules, power cords, cables and peripherals excluded.
- 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
- Fiber cushions made from 100% recycled wood fiber and organic materials.

Manageability

Industry Standard Specifications Intel® Active Management Technology (AMT)

This product meets the following industry standard specifications for manageability functionality:

DASH 1.2 (via Intel[®] LAN on motherboard)

Intel® Active Management Intel® Active Management Technology (AMT) 16.10

An advanced set of remote management features and functionality providing IT administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 16.10 includes the following advanced management functions:

- Power Management (on, off, reset, graceful shutdown, sleep and hibernate)
 - o Support in Max Power Savings (Shutdown and Hibernate Modes)
- Hardware Inventory (includes BIOS and firmware revisions)
- Hardware Alerting
- Agent Presence
- System Defense Filters
- Serial Over LAN (SOL)
- USB Redirect (Media Redirection)
- ME Wake-on-LAN (WOL), even with Maximum Power Savings Enabled
- DASH 1.2 compliance
- IPv6 Support
- Fast Call for Help a client inside or outside the firewall may initiate a call for help via BIOS screen, periodic connections, or alert triggered connection
- Remote Scheduled Maintenance pre-schedule when the system connects to the IT or service provider console for maintenance.
- Remote Alerts automatically alert IT or service provider if issues arise
- Access Monitor Provides oversight into Intel® AMT actions to support security requirements



System Technical Specifications

- PC Alarm Clock
- Microsoft NAP Support
- Host Base set-up and configuration
- Management Engine (ME) firmware roll back
- Local Time Sync to UTC
- Remote Memory Dump Command Creates memory dump for debug

Intel® vPro™ Technology

Yes, when configured with an Intel® vPro™ supporting processor.



Technical Specifications - Stable & Consistent Offerings

Stable & Consistent Offerings

Global Series SKUs

As part of its commitment to hardware, software, and solution innovation, HP is proud to introduce this breakthrough platform configuration stability to HP Workstation customers. HP Stable & Consistent Offerings are built on the foundation of a carefully chosen set of hardware and software designed and tested to work with all HP Z Workstation platforms through their end of life. These components and their corresponding HP Workstation platform compatibility are outlined in this section.

Stable & Consistent Offerings

HP Stable & Consistent Offerings are available worldwide to all HP Workstation customers-no special programs, no additional cost-no kidding. Simply select your hardware and software components when you customize your HP Workstation and be assured that you'll be able to buy that same configuration throughout the lifecycle of the product.

Processors	Product #	Offering
	6M6F2AV	Intel Xeon W3-2423
	57M48AV	Intel Xeon W3-2435
Graphics	Product #	Offering
	6Z2ZOAV	NVIDIA Long-Life T1000E
	6Z2Y4AV	NVIDIA Long-Life RTX A2000E
	6Z2Y6AV	NVIDIA Long-Life RTX A4000E
	695F0AV	AMD Radeon RX 6400
	57K43AV	AMD Radeon Pro 6600
Storage	Product #	Offering
-	57L12AV	Z Turbo 1TB PCIe-4x4 2280 TLC M.2 Solid State Drive
	57K65AV	1TB 7200RPM SATA 3.5in Enterprise



Technical Specifications - Hard Drives

STORAGE/HARD DRIVES

Performance PCIe SSDs for HP Workstations

Z Turbo 512GB 2280 PCIe-4x4 TLC SSD

Capacity 512GB **Protocol** PCIe **Form Factor** M.2 Controller NVMe 3D TLC NAND Type

300TBW (TB Written) **Endurance**

Reliability 1.5M hours

Rated for 24/7/365

operation

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

No

Performance Sequential Read up to 6400MB/s*

> **Sequential Write** up to 3400MB/s* **Random Read** up to 600K IOPS* **Random Write** up to 600K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 512GB 2280 PCIe-4x4 SED **OPAL2 TLC M.2 SSD**

512GB Capacity **Protocol PCIe Form Factor** M.2 Controller NVMe **NAND Type** 3D TLC

Endurance 300TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

PCI Express 4.0 x4 electrical Interface 32° to 158° F (0° to 70° C) Operating Temperature

Nο

Performance Sequential Read up to 6400MB/s*

OPAL 2

Sequential Write up to 3400MB/s* **Random Read** up to 600K IOPS* **Random Write** up to 600K IOPS*

Self-Encrypting Drive

Support

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 1TB 2280 PCIe-4x4 SED **OPAL2 TLC M.2 SSD** Module

Capacity 1TB **PCIe** Protocol **Form Factor** M.2 Controller NVMe **NAND Type** 3D TLC

Endurance 400TBW (TB Written)

Reliability 1.5M hours

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

Rated for 24/7/365

operation

No

Interface PCI Express 4.0 x4 electrical
Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read

Sequential Read up to 6500MB/s*
Sequential Write up to 5000MB/s*
Random Read up to 800K IOPS*
Random Write up to 800K IOPS*

Self-Encrypting Drive

Support

OPAL 2

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 1TB 2280 PCIe-4x4 TLC SSD
 Capacity
 1TB

 Protocol
 PCIe

 Form Factor
 M.2

 Controller
 NVMe

 NAND Type
 3D TLC

Endurance 400TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

No

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance

Sequential Read up to 6500MB/s*
Sequential Write up to 5000MB/s*
Random Read up to 800K IOPS*
Random Write up to 800K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 1TB 2280 PCIe-4x4 TLC SSD
 Capacity
 1TB

 Protocol
 PCIe

 Form Factor
 M.2

 Controller
 NVMe

 NAND Type
 3D TLC

Endurance 400TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

No

Interface PCI Express 4.0 x4 electrical
Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read up to 6500MB/s*

Sequential Write up to 5000MB/s*
Random Read up to 800K IOPS*
Random Write up to 800K IOPS*

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 2TB 2280 PCIe-4x4 SED **OPAL2 TLC M.2 SSD**

2TB Capacity **Protocol** PCIe M.2 **Form Factor** NVMe Controller NAND Type 3D TLC

Endurance 500TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

Performance

PCI Express 4.0 x4 electrical

Interface 32° to 158° F (0° to 70° C) **Operating Temperature**

Nο

Sequential Read up to 6500MB/s* **Sequential Write** up to 5000MB/s* **Random Read** up to 800K IOPS* **Random Write** up to 800K IOPS*

Self-Encrypting Drive OPAL 2

Support

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 2TB 2280 PCIe-4x4 TLC SSD Capacity 2TB PCIe **Protocol Form Factor** M.2 NVMe Controller **NAND Type** 3D TLC

Endurance 500TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

No

Interface PCI Express 4.0 x4 electrical **Operating Temperature** 32° to 158° F (0° to 70° C)

Performance **Sequential Read** up to 6500MB/s*

> **Sequential Write** up to 5000MB/s* **Random Read** up to 800K IOPS* **Random Write** up to 800K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 4TB 2280 PCIe-4x4 TLC M.2 SSD

Capacity 4TB Protocol **PCIe Form Factor** M.2 Controller NVMe **NAND Type** 3D TLC



^{*}Actual performance may vary.

Technical Specifications - Hard Drives

Endurance 600TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365 No

operation

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read up to 6500MB/s*

Sequential Write up to 5000MB/s*
Random Read up to 700K IOPS*
Random Write up to 700K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

NOTE: available in June 2023

Z Turbo 4TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD
 Capacity
 4TB

 Protocol
 PCIe

 Form Factor
 M.2

 Controller
 NVMe

 NAND Type
 3D TLC

Endurance 600TBW (TB Written)

No

Reliability 1.5M hours

Rated for 24/7/365

operation Interface

PCI Express 4.0 x4 electrical

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read up to 6500MB/s*

Sequential Write up to 5000MB/s*
Random Read up to 700K IOPS*
Random Write up to 700K IOPS*

Self-Encrypting Drive OPAL 2

Support

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

NOTE: available in June 2023

Z Turbo 512GB PCIe-4x4 TLC Z4/Z6 Kit SSD

Capacity512GBProtocolPCIeForm FactorM.2ControllerNVMeNAND Type3D TLC

Endurance 300TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

Interface PCI Express 4.0 x4 electrical
Operating Temperature 32° to 158° F (0° to 70° C)

No



^{*}Actual performance may vary.

Technical Specifications - Hard Drives

Performance	Sequential Read	up to 6400MB/s*
	Sequential Write	up to 3400MB/s*
	Random Read	up to 600K IOPS*
	Random Write	up to 600K IOPS*

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 512GB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z4/Z6 Kit SSD

Capacity512GBProtocolPCIeForm FactorM.2ControllerNVMeNAND Type3D TLC

Endurance 300TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

Interface PCI Express 4.0 x4 electrical
Operating Temperature 32° to 158° F (0° to 70° C)

No

Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read up to 6400MB/s*

Sequential Write up to 3400MB/s*
Random Read up to 600K IOPS*
Random Write up to 600K IOPS*

0041.0

1TB

Support

Self-Encrypting Drive

OPAL 2

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 1TB PCIe-4x4 TLC Capacity Z4/Z6 Kit SSD Protocol

Protocol PCIe
Form Factor M.2
Controller NVMe
NAND Type 3D TLC

Endurance 400TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

No

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read up to 6500MB/s*

Sequential Write up to 5000MB/s*

Random Read up to 800K IOPS*

Random Write up to 800K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Capacity 1TB



^{*}Actual performance may vary.

Technical Specifications - Hard Drives

Z Turbo 1TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z4/Z6 Kit SSD

PCIe **Protocol Form Factor** M.2 Controller NVMe **NAND Type** 3D TLC

Endurance 400TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

PCI Express 4.0 x4 electrical

Interface Operating Temperature 32° to 158° F (0° to 70° C)

No

Performance Sequential Read up to 6500MB/s*

> Sequential Write up to 5000MB/s* **Random Read** up to 800K IOPS* **Random Write** up to 800K IOPS*

Self-Encrypting Drive OPAL 2

Support

*Actual performance may vary. NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 2TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z4/Z6 Kit SSD

Capacity 2TB Protocol PCIe **Form Factor** M.2 NVMe Controller **NAND Type** 3D TLC

Endurance 500TBW (TB Written)

Reliability 1.5M hours

Rated for 24/7/365

operation

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Nο

Performance Sequential Read up to 6500MB/s*

> **Sequential Write** up to 5000MB/s* **Random Read** up to 800K IOPS* **Random Write** up to 800K IOPS*

OPAL 2

Self-Encrypting Drive

Support

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Z Turbo 4TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z4/Z6 Kit SSD

4TB Capacity **PCIe Protocol Form Factor** M.2 Controller NVMe **NAND Type** 3D TLC

Endurance 600TBW (TB Written)

Reliability 1.5M hours

up to 6500MB/s*

Technical Specifications - Hard Drives

Rated for 24/7/365

operation

Nο

Interface PCI Express 4.0 x4 electrical **Operating Temperature** 32° to 158° F (0° to 70° C)

Performance Sequential Read

Sequential Write up to 5000MB/s* **Random Read** up to 700K IOPS* **Random Write** up to 700K IOPS*

Self-Encrypting Drive

Support

OPAL 2

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

NOTE: available in June 2023

SATA Hard Drives for HP Workstations

1TB 7200RPM SATA 3.5in Capacity **Enterprise HDD**

1TB **Protocol** SATA 3.5" **Form Factor** Controller AHCI Reliability 2.0M hours **Rated Power On Hours** 8760/yr

Annualized Failure Rate (based on Rated POH)

YES

<0.62%

Rated for 24/7/365

operation

1 in; 2.54 cm

Height Width **Media Diameter**

> **Physical Size** 4 in; 10.17 cm

3.5 in: 8.9 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s *

Buffer 128MB Cache Adaptive

Seek Time (typical reads, Single Track 0.32 ms * includes controller 7.45 ms * Average overhead, including **Full Stroke** 14.2 ms * settling)

Rotational Speed 7,200 rpm **Logical Blocks** 1,953,525,168

Operating Temperature 41° to 131° F (5° to 55° C)

Performance Sequential Read up to 226MB/s* **Sequential Write** up to 226MB/s*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

2TB 7200RPM SATA 3.5in Capacity 2TB **Enterprise HDD** Protocol SATA



^{*}Actual performance may vary.

Technical Specifications - Hard Drives

Form Factor 3.5" Controller **AHCI** Reliability 2.0M hours **Rated Power On Hours** 8760/yr **Annualized Failure Rate** <0.62%

(based on Rated POH)

Rated for 24/7/365

operation

Height

1 in: 2.54 cm

YES

Width **Media Diameter** 3.5 in: 8.9 cm

> **Physical Size** 4 in: 10.17 cm

Interface Serial ATA (6.0Gb/s). NCO enabled

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s *

Buffer 128MB Cache Adaptive

Seek Time (typical reads, includes controller overhead, including settling)

Average

Single Track

0.7 ms * 8.5 ms *

Full Stroke

15.7 ms *

Rotational Speed 7,200 rpm **Logical Blocks** 3.907.029.168

Operating Temperature

41° to 131° F (5° to 55° C) **Performance**

Sequential Read up to 226MB/s* **Sequential Write** up to 226MB/s*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

4TB 7200 RPM SATA 3.5in Capacity 4TB **Enterprise HDD** Protocol **SATA**

3.5" **Form Factor** Controller **AHCI** Reliability 2.0M hours **Rated Power On Hours** 8760/yr **Annualized Failure Rate** < 0.62%

(based on Rated POH)

Rated for 24/7/365 YES

operation

Height 1 in; 2.54 cm

Media Diameter Width 3.5 in; 8.9 cm **Physical Size** 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s *

Buffer 256MB Cache Adaptive

> Single Track 0.7 ms *



^{*}Actual performance may vary.

Technical Specifications - Hard Drives

Seek Time (typical reads, includes controllerAverage8.5 ms *Full Stroke15.7 ms *

overhead, including

settling)

Rotational Speed 7,200 rpm **Logical Blocks** 7,814,037,168

Operating Temperature 41° to 131° F (5° to 55° C)

Performance Sequential Read up to 226MB/s*
Sequential Write up to 226MB/s*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

8TB 7200RPM SATA 3.5in Capacity
Enterprise HDD Protocol

 Protocol
 SATA

 Form Factor
 3.5"

 Controller
 AHCI

 Reliability
 2.0M hours

 Rated Power On Hours
 8760/yr

 Annualized Failure Rate
 <0.62%</th>

(based on Rated POH)

Rated for 24/7/365 YES

operation

Height

1 in: 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm

Physical Size 4 in; 10.17 cm

0.7 ms *

8.5 ms *

15.7 ms *

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s *

Buffer 256MB Cache Adaptive

Seek Time (typical reads, includes controller overhead, including settling)

Single Track

Average

Full Stroke

Rotational Speed 7,200 rpm

Logical Blocks 15,628,053,168

Operating Temperature 41° to 140° F (5° to 60° C)

Performance Sequential Read up to 226MB/s*
Sequential Write up to 226MB/s*

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

12TB 7200 RPM SATA-6G Capacity
3.5in Enterprise HDD Protocol

Capacity 12TB
Protocol SATA
Form Factor 3.5"
Controller AHCI
Reliability 2.0M hours



^{*}Actual performance may vary.

Technical Specifications - Hard Drives

Rated Power On Hours 8760/yr **Annualized Failure Rate** <0.62%

(based on Rated POH)

Rated for 24/7/365 YES

operation

Height 1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm

Physical Size 4 in; 10.17 cm

0.7 ms *

8.5 ms *

15.7 ms *

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s *

256MB

Buffer 256MB
Cache Adaptive
Seek Time (typical reads, Single Track

includes controller Average overhead, including settling) Full Stroke

Rotational Speed 7,200 rpm Logical Blocks 23,437,770,752

Operating Temperature 41° to 140° F (5° to 60° C)

Performance Sequential Read up to 226MB/s*
Sequential Write up to 226MB/s*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

^{*}Actual performance may vary.

Technical Specifications - Graphics

GRAPHICS

NVIDIA® RTX™ 6000

Ada 48GB

Form Factor Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 1230 grams / 2.71 lbs (with extender)

Max PowerPower: 300 WattsConsumptionCooling: Active

GPU Memory 48GB GDDR6 memory ECC

Memory Bandwidth: Up to 960 GB/s

Memory Width: 384 bits

Connectors 4x DisplayPort 1.4a

Quadro Sync II connector

Stereo Sync

Requires CEM 5.0 16-pin auxiliary power adapter

Maximum Resolution

Bus Type Available Graphics 7680x4320 @ 120Hz PCI Express 4.0 x16

Windows 11

Drivers Windows 10 Linux® 64-bit

NOTE: available in June 2023

NVIDIA® RTX™ A6000

48GB

Form Factor Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 1230 grams / 2.71 lbs (with extender)

Max Power Consumption Power: 300 Watts

Cooling: Active

GPU Memory 48GB GDDR6 memory

ECC optional

Memory Bandwidth: Up to 768 GB/s

Memory Width: 384 bit

Connectors 4x DisplayPort 1.4a

Quadro Sync II connector

NVLink®

Stereo Sync

Requires 8-pin auxiliary power

Maximum Resolution

7680x4320 @ 120Hz

Bus Type

PCI Express 4.0 x16

Available Graphics

Windows 11

Drivers

Windows 10 Linux® 64-bit

NVIDIA® RTX™ A5000

24GB

Form Factor Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 1049 grams + 80 grams extender

Max Power Consumption Power: 230W

Cooling: Active

GPU Memory 24GB GDDR6 memory

ECC optional

Memory Bandwidth: Up to 768 GB/s

Memory Width: 384 bit

Connectors 4x DisplayPort 1.4a

Quadro Sync II connector

NVLink® Stereo Sync

Requires 8-pin auxiliary power

Technical Specifications - Graphics

Maximum Resolution 7680x4320 @ 120Hz **Bus Type** PCI Express 4.0 x16

Available Graphics

Drivers

Windows 11 Windows 10 Linux® 64-bit

NVIDIA® RTX A4500 20GB Form Factor Full-Height Dual Slot (4.4" Height x 10.5" Length)

Weight: 1049 grams + 80 grams extender

Power: 200W Max Power Consumption

Cooling: Active

GPU Memory 20GB GDDR6 memory

Memory Bandwidth: Up to 640 GB/s

Memory Width: 320 bit

4x DisplayPort 1.4a **Connectors**

Quadro Sync II connector

NVLink® Stereo Sync

Requires 8-pin auxiliary power

Maximum Resolution

Bus Type

PCI Express 4.0 x16

7680x4320 @ 120Hz

Available Graphics

Drivers

Windows 11 Windows 10 Linux® 64-bit

NVIDIA® RTX A4000 16GB Form Factor Full-Height Single Slot (4.4" Height x 9.5" Length)

Weight: 500 grams

Max Power Consumption Power: 140W

Cooling: Active

GPU Memory 16GB GDDR6 memory

Memory Bandwidth: Up to 448 GB/s

Memory Width: 256 bit

4x DisplayPort 1.4a **Connectors**

Quadro Sync II connector

Stereo Sync

Requires 6-pin auxiliary power

Maximum Resolution

7680x4320 @ 120Hz PCI Express 4.0 x16

Available Graphics

Windows 11

Drivers

Bus Type

Windows 10

Linux® 64-bit

NVIDIA® Long-Life RTX A4000E 16GB

Form Factor

Full-Height Single Slot (4.4" Height

x 9.5" Length) Weight: 500 grams

Max Power Consumption Power: 140W

Cooling: Active

16GB GDDR6 memory **GPU Memory**

Memory Bandwidth: Up to 448 GB/s

Memory Width: 256 bit

Technical Specifications - Graphics

4x DisplayPort 1.4a Connectors

Quadro Sync II connector

Stereo Sync

Requires 6-pin auxiliary power

Maximum Resolution 7680x4320 @ 120Hz **Bus Type** PCI Express 4.0 x16

Available Graphics

Windows 11 **Drivers** Windows 10

Linux® 64-bit

NOTE: available in June 2023

AMD® Radeon™ Pro W6800 32GB

Form Factor Full-Height Dual Slot (4.4" Height x

10.5" Length)

Weight: 850 grams Max Power Consumption Power: 261W

Cooling: Active

GPU Memory 32GB GDDR6 memory

Memory Bandwidth: Up to 512 GB/s

Memory Width: 256 bit

6x mini-DisplayPort 1.4 Connectors

Requires 8-pin+6-pin auxiliary power

Maximum Resolution 7680x4320 @ 60Hz

Bus Type PCI Express 4.0 x16

Available Graphics

Drivers

Windows 11 Windows 10 Linux® 64-bit

NVIDIA® RTX A2000 12GB Form Factor Half-Height Dual Slot (2.713"

Height x 6.6" Length)

Weight: 306 grams

Max Power Consumption Power: 70W

Cooling: Active

GPU Memory 12GB GDDR6 memory

Memory Bandwidth: Up to 288 GB/s

Memory Width: 192 bit

Connectors 4x mini-DisplayPort 1.4a **Maximum Resolution** 7680x4320 @ 120Hz **Bus Type** PCI Express 4.0 x16

Available Graphics

Drivers

Windows 11 Windows 10 Linux® 64-bit

NVIDIA® Long-Life RTX A2000E 12GB

Form Factor Half-Height Dual Slot (2.713"

> Height x 6.6" Length) Weight: 306 grams

Max Power Consumption Power: 70W

Cooling: Active

Technical Specifications - Graphics

GPU Memory 12GB GDDR6 memory

Memory Bandwidth: Up to 288 GB/s

Memory Width: 192 bit

4x mini-DisplayPort 1.4a **Connectors Maximum Resolution** 7680x4320 @ 120Hz **Bus Type** PCI Express 4.0 x16

Available Graphics

Drivers

Windows 11 Windows 10

Linux® 64-bit

NVIDIA® T1000 8GB Form Factor Half-Height Single Slot (2.713"

Height x 6.137" Length) Weight: 132.6 grams

Max Power Consumption Power: 50W

Cooling: Active

GPU Memory 8GB GDDR6 memory

Memory Bandwidth: Up to 160 GB/s

Memory Width: 128 bit

Connectors 4x mini-DisplayPort 1.4a **Maximum Resolution** 7680x4320 @ 120Hz PCI Express 3.0 x16

Bus Type

Available Graphics

Drivers

Windows 11

Windows 10 Linux® 64-bit

NVIDIA® Long-Life **T1000E 8GB**

Form Factor Half-Height Single Slot (2.713"

> Height x 6.137" Length) Weight: 132.6 grams

Power: 50W **Max Power Consumption**

Cooling: Active

8GB GDDR6 memory **GPU Memory**

Memory Bandwidth: Up to 160 GB/s

Memory Width: 128 bit

Connectors 4x mini-DisplayPort 1.4a **Maximum Resolution** 7680x4320 @ 120Hz **Bus Type** PCI Express 3.0 x16

Available Graphics

Drivers

Windows 11 Windows 10 Linux® 64-bit

NVIDIA® T1000 4GB Form Factor Half-Height Single Slot (2.713"

> Height x 6.137" Length) Weight: 132.6 grams

Max Power Consumption Power: 50W

Cooling: Active

GPU Memory 4GB GDDR6 memory

Memory Bandwidth: Up to 160 GB/s

Memory Width: 128 bit

Connectors 4x mini-DisplayPort 1.4a

Technical Specifications - Graphics

Maximum Resolution 7680x4320 @ 120Hz

Bus Type PCI Express 3.0 x16

Available Graphics

Drivers Windows 10

Linux® 64-bit

Windows 11

AMD® Radeon™ Pro W6600 8GB **Form Factor** Full-Height Single Slot (4.38"

Height x 9.50" Length) Weight: 132.6 grams

Max Power Consumption Power: 122W

Cooling: Active

GPU Memory 8GB GDDR6 memory

Memory Bandwidth: Up to 224 GB/s

Memory Width: 128 bit

Connectors 4x DisplayPort 1.4

Requires 6-pin auxiliary power

Maximum Resolution 7680x4320 @ 60Hz

Bus Type

PCI Express 4.0 x16 (x8 electrical)

Available Graphics

Drivers

Windows 11 Windows 10

Linux® 64-bit

AMD® Radeon™ RX 6700XT 12GB **Form Factor** Full-Height Dual Slot (4.30" Height

x 10.0" Length) Weight: 684 grams

Max Power Consumption Power: 238W

Cooling: Active

GPU Memory 12GB GDDR6 memory

Memory Bandwidth: Up to 384 GB/s

Memory Width: 192 bit

Connectors 4x DisplayPort 1.4

1x HDMI

Requires 8-pin+6-pin auxiliary power

Maximum Resolution

Bus Type

7680x4320 @ 60Hz

Available Graphics

Drivers

PCI Express 4.0 x16

Windows 11 Windows 10 Linux® 64-bit

NVIDIA® T400 4GB Form Factor Half-Height Single Slot (2.713"

Height x 6.137" Length) Weight: 123.5 grams

Max Power Consumption Power: 30W

Cooling: Active

GPU Memory 4GB GDDR6 memory

Memory Bandwidth: Up to 80 GB/s

Memory Width: 64 bit

Connectors 3x mini-DisplayPort 1.4a **Maximum Resolution** 7680x4320 @ 120Hz

Technical Specifications - Graphics

Bus Type PCI Express 3.0 x16

Available Graphics Windows 11
Drivers Windows 10

Linux® 64-bit

AMD® Radeon™ RX 6400

4GB

Form Factor Half-Height Single Slot (4.4"

Height x 10.5" Length)

Weight: 155 grams

Max Power Consumption Power: 50W

Cooling: Active

GPU Memory 4GB GDDR6 memory

Memory Bandwidth: Memory Width:

Connectors 1x DisplayPort 1.4a

1x HDMI

Maximum Resolution7680x4320 @ 60HzBus TypePCI Express 4.0 x4

Available Graphics

Drivers

Windows 11 Windows 10 Linux® 64-bit

Intel® Arc Pro A40 6GB Form Factor Half-Height Single Slot (2.7"

Height x 6.6" Length)

Weight: 220 grams

Max Power Consumption Power: 50W

Cooling: Active

GPU Memory 4GB GDDR6 memory

Memory Bandwidth: 192GB

Memory Width: 96 bit

Connectors 4x mini- DisplayPort 1.4

Maximum Resolution 7680x4320 @ 60Hz

Bus Type PCI Express 4.0 x8

Available Graphics Windows 11

Drivers Windows 10

NOTE: available in June 2023

Notes for all graphics cards:

- Some graphics and GPU compute cards can consume a great deal of power, thus combinations of cards with other components may exceed a particular power supply's output capability.
- Some graphics and GPU compute cards require supplemental power cables.
- Not all chassis/PSU configurations have enough supplemental power cables of the correct type for all graphics configurations.

Refer to the Power Supply section within Overview for more information.

OPTICAL AND REMOVABLE STORAGE



Technical Specifications - Graphics

HP 9.5mm Slim Blu-Rav Writer

Description 9.5mm height, trav-load **Mounting Orientation** Either horizontal or vertical

Interface Type SATA/ATAPI

Dimensions (WxHxD) 128 x 9.5 x 127mm

Supported Media Types BD-ROM

BD-R **BD-RE** DVD+R DVD+RW DVD+R DL DVD-R DI DVD-R DVD-RW CD-R CD-RW

Disc Capacity DVD-ROM 8.5 GB DL or 4.7 GB standard

> 25 GB (single-layer) Blu-ray

50 GB (dual-layer) 100/128 GB (BDXL)

Full Stroke DVD < 230 ms (seek) **Full Stroke CD** < 220 ms (seek)

Blu-ray < 230 ms (seek) (Full Stroke Blu-ray) **Startup Time** (Time to drive ready from tray loading)

BD-ROM (SL/DL) 255 / 285 BD-R (SL/DL) 255 / 285 BD-RE (SL/DL) 255 / 285 DVD-ROM (SL/DL) 18S / 18S DVD-R (SL/DL) 25S / 25S

DVD-RW **25S**

DVD+R (SL/DL) 255 / 255

DVD+RW **25S** CD-ROM **15S**

Maximum Data Transfer CD ROM Read Rates

CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

DVD ROM Read DVD+RW Up to 8X

> DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X

Blu-ray BD-ROM Up to 6X

BD-ROM DL Up to 6X BD-R Up to 6X BD-R DL Up to 6X BD-R Up to 6X BD-RE SL/DL Up to 6X

Power Source SATA DC power receptacle

> **DC Power Requirements** 5 VDC ± 5%-100 mV ripple p-p

Technical Specifications - Graphics

DC Current 5 VDC -900 mA typical, 2000mA

Operating Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions noncondensina)

Relative Humidity 10% to 80% **Maximum Wet Bulb** 84° F (29° C)

Temperature

Operating Systems Supported

Windows 11, Windows 10, Windows 7 Professional 64-bit, Red Hat® Enterprise Linux® (RHEL) 8, 9 Desktop/Workstation

SUSE Linux® Enterprise Desktop 15

Ubuntu 20.04, 22.04 LTS

No driver is required for this device. Native support is provided by the

operating system.

Kit Contents 9.5mm Slim BDXL Blu-Ray Writer, 5.25" ODD Bay adapter/carrier, slim

SATA data/power cable, installation guide

As Blu-ray is a new format containing new technologies, certain disc. digital connection, compatibility and/or performance issues may arise, and do not constitute defects in the product. Flawless playback on all systems is not guaranteed. In order for some Blu-ray titles to play, they may require a DVI or HDMI digital connection and your display may require HDCP support. HD-DVD movies cannot be played on this workstation.

NOTE: HD-DVD disks cannot be played on the DVD-ROM drive. No support for DVD-RAM. Actual speeds may vary. Don't copy copyright-protected materials. Double Layer discs can store more data than single layer discs. Discs burned with this drive may not be compatible with many existing single-layer DVD drives and players. Flawless playback on all systems is not guaranteed.

HP 9.5mm Slim DVD Writer

Description 9.5mm height, tray-load **Mounting Orientation** Either horizontal or vertical

Interface Type SATA/ATAPI

Dimensions (WxHxD) 128 x 9.5 x 127mm

Supported Media Types DVD+R

> DVD+RW DVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW

DVD-ROM 8.5 GB DL or 4.7 GB standard **Disc Capacity**

> **Full Stroke DVD** < 200 ms (seek) **Full Stroke CD** < 200 ms (seek)

Maximum Data Transfer CD ROM Read

Rates

CD-ROM, CD-R Up to 24X

CD-RW Up to 24X

DVD ROM Read DVD+RW Up to 8X

> DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X

Technical Specifications - Graphics

DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X

Power Source SATA DC power receptacle

DC Power Requirements 5 VDC ± 5%-100 mV ripple p-p

DC Current 5 VDC -< 800 mA typical, <1600 mA maximum

Operating Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions noncondensing)

Relative Humidity 10% to 80% Maximum Wet Bulb 84° F (29° C)

Temperature

Operating Systems
Supported

Windows 11, Windows 10, Windows 7 Professional 64-bit,

Windows Vista Business 64*, Windows 2000.

Red Hat® Enterprise Linux® (RHEL) 8, 9 Desktop/Workstation

SUSE Linux® Enterprise Desktop 15

Ubuntu 20.04, 22.04 LTS

* No driver is required for this device. Native support is provided by the

operating system

Kit Contents HP SATA DVD Writer drive, installation guide.

NOTE: Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.



Technical Specifications - Optical and Removable Storage

HP 9.5mm Slim DVD-ROM Description 9.5mm height, tray-load

Mounting Orientation Either horizontal or vertical

Interface Type SATA/ATAPI

Dimensions (WxHxD) 128 x 9.5 x 127mm

Disc Capacity DVD-ROM Single layer: Up to 4.7 GB

Double laver: Up to 8.5 GB

Access Times DVD-ROM Single Layer < 110 ms (typical)

> < 110 ms (typical) **CD-ROM Mode 1 Full Stroke DVD** < 230 ms (typical) **Full Stroke CD** < 220 ms (typical)

Power SATA DC power receptacle Source

> **DC Power Requirements** 5 VDC ± 5%-100 mV ripple p-p

DC Current 5 VDC -< 800 mA typical, <1600 mA maximum

Operating Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions non-

Relative Humidity 10% to 80% condensing) **Maximum Wet Bulb** 84° F (29° C)

Temperature

Operating Systems

Windows 11. Windows 10. Windows 8.1. Windows 7 Professional 64-bit Supported Red Hat® Enterprise Linux® (RHEL) 8, 9 Desktop/Workstation

SUSE Linux® Enterprise Desktop 15

Ubuntu 20.04, 22.04 LTS

No driver is required for this device. Native support is provided by the

operating system.

Kit Contents 9.5mm Slim DVD-ROM Drive, 5.25" ODD Bay adapter/carrier, slim SATA

data/power cable, installation guide

NOTE: Actual speeds may vary. No support for DVD-RAM (DVD Writer). Does not permit copying of commercially available DVD movies or other copyright protected materials. Intended for creation and storage of your original material and other lawful uses. Double Layer discs can store more data than single layer discs. However, double-layer discs burned with this drive may not be compatible with many existing single-layer DVD drives and players.



Technical Specifications - Networking and Communications

NETWORKING AND COMMUNICATIONS

HP 10GBase-T Flex Port Connector RJ-45 (Single Port)

> Cabling Twisted Pair Cabling, up to 100 meters

Controller Marvell AQC113C

Memory 128KB Tx Buffer, 192KB Rx Buffer on-chip **Data Rates Supported** 10/100/1000 Mbps and 2.5/5/10 Gbps

Compliance 802.3 - 2018, 802.1AS-2011 **Bus Architecture** PCI Express and SMBus

Data Transfer Mode PCIe-based interface for active state operation (SO state) and SMBus for

host and management traffic

Power Requirement Requires 0.7V VDD, 1V, and 2V for analog, 3.3V for VDDIO

Boot ROM Support Yes

Network Transfer Mode Full-duplex **Network Transfer Rate** 10GBASE-T

5GBASE-T 2.5GBASE-T 1000BASE-T 100BASE-TX 10BASE-Te

Management Capabilities WOL, PXE, UEFI,

Kit Contents HP 10GBase-T Flex Port NIC Module

HP 2.5GbE LAN Flex Port Connector RJ45 (Single Port)

> Cabling Copper twisted pair, Cat5e up to 100 meters

Controller Intel® I225-V

4 Tx and 4 Rx Queues, Jumbo Frames up to 9KB and without TSN Memory

10/100/1000Mbps and 2.5Gbps BASE-T **Data Rates Supported**

IEEE 802.3, 802.3u (auto-negotiation), 802.3ab, 1588, 802.1AS-Rev, Compliance

802.1Qav, 802.1Qbu, 802.1Qbv, 802.3br, 802.3az

Bus Architecture PCIe G2x1

Data Transfer Mode PCIe-based interface for active state operation (SO state) and SMBus for

host and management traffic (Sx low power state)

Power Requirements 2.2 Watts

Network Transfer Mode Automatic link configuration for speed duplex and flow control

Network Transfer Rate 2500BASE-T 1000BASE-T

100BASE-TX (Half-duplex supported) 10BASE-Te (Half-duplex supported)

Management Capabilities WOL, PXE, UEFI, Intel vPro® support with appropriate Intel Chipset, Error

Correcting Memory in packet buffers, UDP/TCP/IP Checksum Offload, SCTP

receive and transmit integrity offload

LC (Little Connector) Fiber (Single Port)

Kit Contents HP 2.5GbE LAN Flex Port Networking Interface Card

HP 1GbE Fiber LC Single Flex Port

Connector

Cabling LC Fiber Cabling

Technical Specifications - Networking and Communications

Controller AT-29M2

Data Rates Supported 1GBASE-SX

Bus Architecture USB 3.1G1

Power Requirements Up to 3.3 Watts

Network Transfer Mode 1GBASE-SX

Network Transfer Rate 1GBASE-SX

Management Capabilities Wake on LAN, Digital Diagnostic Monitoring

Kit Contents HP 1GbE Fiber LC Single Flex Port NIC

HP Flex 1GbE Single Port NIC

Connector RJ45 (Single Port)

Cabling 1GbE over Category 5e (or better) up to 100m

ControllerRealtek RTL8153Data Rates Supported10/100/1000 MbpsBus ArchitectureUSB3.1G1, USB2

Power Requirements Requires 3.3V (integrated regulators for core Vdc)

Wake on LAN, PXE, UEFI

Network Transfer Mode Full-duplex; Half-duplex

Network Transfer Rate 10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps

Management Capabilities

Kit Contents HP 1GbE Single Flex Port

Intel® X550 10GBASE-T Dual Port NIC **Connector** 2 x RJ-45

Cabling Cat5 (or higher) for 100Mbps

Cat5e (or higher) for 1Gbps, 2.5Gbps, or 5Gbps Cat6 (or higher) for 10Gbps up to 55m Cat6a (or higher) for 10Gbps up to 100m

Controller Intel X550-AT2

Memory Jumbo Frames up to 15.5KB, 64 Tx and 64Rx Queues per port, 160KB/port

of programmable memory transmit buffers

Data Rates Supported

100Mbps (BASE-TX), 1Gbps (BASE-T, 2.5Gbps, 5Gbps, 10Gbps

Compliance 802.1q (VLAN), 802.1Qbb, 802.1p, 802.1Qaz

Bus Architecture PCle 3x4

Data Transfer Mode PCle Gen 3 x4 based interface

Power Requirements 3.9W at 100Mbps 5.5W at 1Gbps

11.2W at 10Gbps

Boot ROM Support Yes

Network Transfer Mode Auto negotiation between 1GbE, 2.5GbE, 5GbE and 10GbE

Management Capabilities DMI 2.0 Support, Windows Management Instrumentation (WMI) and SNMP,

PXE 2.0 through boot ROM, Multi-mode I/O Virtualization, VxLAN, VMDg,

VLAN support with VLAN tag insertion

Kit Contents Intel® X550 10GBASE-T Dual Port NIC

Technical Specifications - Networking and Communications

Intel® 1225-T1 Single Port 2.5GbE PCIe NIC

Connector RJ-45 (Single Port)

Cabling Cat5e (or better) up to 100m Controller Intel® Ethernet I225 Controller

Memory Jumbo Frames up to 9.5KB, 4 Tx and Rx Queues.

Data Rates Supported 2.5GbE, 1GbE, 100MbE, 10MbE

Compliance IEEE 802.3 auto negotiation, 802.3x, 802.3z

Bus Architecture PCIe Gen 3.1x1

Data Transfer Mode PCIe-based interface for active state operation

Power Requirements 1.9 Watts (typical)

Management Capabilities WOL, PXE 2.1, Power Management Protocol Offload (proxying), MAC Power

Management, Active State Power Management,

Kit Contents Intel® I225-T1 1-Port 2.5GbE NIC with standard height bracket attached

and Low-profile bracket included

Product Literature

Intel® Ethernet 1350-T4V2 4-Port 1Gb NIC

Connector 4x RJ-45 (Quad Port)

Cabling Cat3 (or higher) for 10Mbps

Cat5 (or higher) for 100Mbps

Cat5e (or higher) for 1Gbps up to 100m

Controller Intel® 1350

Memory Jumbo Frames up to 9.5KB, 8 Tx/Rx Queue pairs per port, Main Internal

memory is Error Code Correcting

Data Rates Supported

10Mbps, 100Mbps, 1Gbps Compliance

IEEE 802.3 auto negotiation, 802.3, 802.3u, 802.3ab, 802.3x, 802.3z,

IEEE1588 protocol and 802.1AS implementation, 802.3az EEE

Bus Architecture PCI Express 2.1 x4

Data Transfer Mode PCIe-based interface for active state operation

Power Requirements

Network Transfer Mode Multi-speed, full, and half-duplex

Network Transfer Rate 10BASE-T

> 100BASE-Tx 1000BASE-T

Management Capabilities WOL, PXE 2.1, UEFI, Power Management Protocol Offload (proxying), MAC

Power Management, Active State Power Management, VLAN, ACPI

Kit Contents Intel® Ethernet I350-T4V2 4-Port 1Gb NIC with full-height bracket installed

Low-profile bracket included

Intel® AX210 Wi-Fi 6 + Bluetooth® 5.2 Flex Port **NIC** with Internal Antennae

Connector Wireless Cabling N/A

Controller Intel® AX210

Wi-Fi 6 (2.4GHz/5GHz) **Data Rates Supported**

Compliance Wi-Fi Alliance* Wi-Fi Alliance CERTIFIED 6, WiFi CERTIFIED a/b/q/n/ac,

WMM, WMM-Power Save, WPA2, WPA3, Wi-Fi Direct, and Wi-Fi Agile

Multiband

IEEE WLAN Standard 802.11-2016, 802.11a, b, d, e, g, h, I, k, n, r, u, v, w, ac,

and ax, Bluetooth® 5.2

Bus Architecture PCIe G3x1 for WLAN, USB3.1G1 for BT



Technical Specifications - Networking and Communications

Management Capabilities Authentication Protocols: 802.1X EAP-TLS, EAP-TTLS/MSCHAPv2, PEAPv0 -

MSCHAPv2 (EAP-SIM, EAP-AKA, EAP-AKA')

Encryption: 128-bit AES-CCMP, 256-bit AES-GCMP

UEFI

Kit Contents Intel® AX210 Wi-Fi 6 + Bluetooth® 5.2 Flex Port NIC

Installation Instructions

* Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 (802.11ax) is backwards compatible with prior 802.11 specs.

Intel® AX210 Wi-Fi 6E non-vPro + Bluetooth® 5.2 with External Antennae WLAN Connector Wireless Cabling N/A

Controller Intel® AX210

Data Rates Supported Wi-Fi 6e (2.4GHz/5GHz/6GHz)

Compliance Wi-Fi Alliance* Wi-Fi Alliance CERTIFIED 6, WiFi CERTIFIED a/b/g/n/ac,

WMM, WMM-Power Save, WPA2, WPA3, Wi-Fi Direct, and Wi-Fi Agile

Multiband

IEEE WLAN Standard 802.11-2016, 802.11a, b, d, e, g, h, I, k, n, r, u, v, w, ac,

and ax, Bluetooth® 5.2

Bus Architecture PCIe G3x1 for WLAN, USB3.1G1 for BT

Management Capabilities Authentication Protocols: 802.1X EAP-TLS, EAP-TTLS/MSCHAPv2, PEAPv0 -

MSCHAPv2 (EAP-SIM, EAP-AKA, EAP-AKA')

Encryption: 128-bit AES-CCMP, 256-bit AES-GCMP

UEFI

Kit Contents Intel® AX210 Wi-Fi 6 + Bluetooth® 5.2 PCIe NIC

External Dipole Antenna Installation Instructions

*Wi-Fi 6E requires a Wi-Fi 6E router, sold separately to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported.

Allies Telesis AT-2914SX/LC 1GB LC Fiber NIC

Connector LC Fiber (Single Port)

Cabling 50/125 μm (core/cladding) multimode fiber optic cable up to 500m

62.5/125 µm (core/cladding) multimode fiber optic cable up to 220m

Memory Jumbo Frames up to 9.6KB

Data Rates Supported

1000SX (1GbE Fiber at 850nm Wavelength)

Compliance

IEEE 802.1p (Quality of Service), IEEE 802.1Q (VLANS), IEEE 802.2 (LLC), IEEE 802.3ac (MAC), IEEE 802.3x (Flow control auto-negotiation), IEEE

802.3z (1000 Base-X), IEEE 802.3ad (Link aggregation)

RoHS, UL, FCC/EN55022 Class A, TUV, EN55024, CE, C-TICK, VCCI

Bus Architecture PCle x1

Data Transfer Mode PCIe-based interface **Power Requirements** 1.5 Watts (typical)

Network Transfer Rate 1000SX only (1GbE Fiber at 850nm Wavelength)

Management Capabilities UEFI, Smart Load Balancing and failover, Link aggregation (IEEE802.3ad),

Generic trunking (FEC/GEC) / IEEE 802.3ad-draft static, VLAN Support

Kit Contents Allied Telesis AT-2914SX/LC 1GB LC Fiber NIC with low-profile bracket

attached and standard height bracket included

Technical Specifications - Networking and Communications

Allied Telesis AT-2911T/2-901 Dual Port 1GbE NIC Connector 2 x RJ-45 (Dual Port)

Cabling Cat3 (or higher) for 10Mbps
Cat5 (or higher) for 100Mbps

Cat5e (or higher) for 1Gbps up to 100m

Memory 17 Rx and 16 Tx queues

Data Rates Supported 10/100/1000 Mbps

Compliance IEEE 802.1p (Quality of Service), IEEE 802.1Q (VLANs), IEEE 802.2 (LLC),

IEEE 802.3ac (MAC), IEEE 802.3x (Flow control auto-negotiation), IEEE 802.3z (1000 Base-X), IEEE 802.3ad (Link aggregation), IEEE 802.3ab

(10/100/1000T)

RoHS, UL, FCC/EN55022 Class A, TUV, EN55024, CE, C-TICK, VCCI

Bus Architecture PCle 2x1

Data Transfer ModePCIe-based interfacePower Requirements2.4 Watts (typical)

Management Capabilities VLAN support, Link aggregation LACP, Link aggregation smart switch,

Failover, Smart Load Balancing (SLB), iSCSI boot support, Windows

Management Instrumentation (WMI), PXE 2.1, SNMP

Kit Contents Allied Telesis AT-2911T/2-901 Dual Port 1GbE NIC with low-profile bracket

attached and standard bracket included



Technical Specifications - Networking and Communications

NVIDIA® Mellanox® ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC

Connector 2 x SFP28 Transceiver Cage (Dual Port)*

Cabling Depends on transceiver pairing. Typically OM4 or higher MMF LC fiber optic

cabling with LC SFP28 Transceivers.

Controller ConnectX6-DX

Memory 256Mbit SPI Quad Flash Device

Data Rates Supported 1/10/25GbE

Compliance – IEEE 802.3by 25 Gigabit Ethernet

- IEEE 802.3ae 10 Gigabit Ethernet

- IEEE 802.3ap based auto-negotiation and KR startup

- IEEE 802.3ad, 802.1AX Link Aggregation - IEEE 802.1Q, 802.1P VLAN tags and priority

- IEEE 802.1Qau (QCN)
- Congestion Notification
- IEEE 802.1Qaz (ETS)
- IEEE 802.1Qbb (PFC)
- IEEE 802.1Qbg
- IEEE 1588v2

Jumbo frame support (9.6KB)Safety: CB/cTUVus/CEEMC: CE/FCC/VCCI/RCMROHS Compliant

-KCC

- CAN ICES-3 (B)

- NM EN 55035/55032 (Morocco)

- UKCA

Bus Architecture PCIe Gen 4 x8

Data Transfer Mode PCI Express - stores and accesses Ethernet fabric connection information

and packet data

Power Requirements 11.5 Watts (typical) **Network Transfer Rate** 1Gbps, 10Gbps, 25Gbps

NOTE: Network Transfer Rate depends on transceiver model.*

Kit Contents NVIDIA® Mellanox® ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC

Date of change:	Version History:		Description of change:	
March 1, 2023	From v1 to v2	Changed	Optical and Removable Storage, Networking and Communications sections and Changed Format	
March 30, 2023	From v2 to v3	Changed	lmage page 1	
April 1, 2023	From v3 to v4	Changed	Format	
April 6, 2023	From v4 to v5	Changed	PCIe Solid State Drives section	
May 1, 2023	From v5 to v6	Changed	Power Supply section	



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